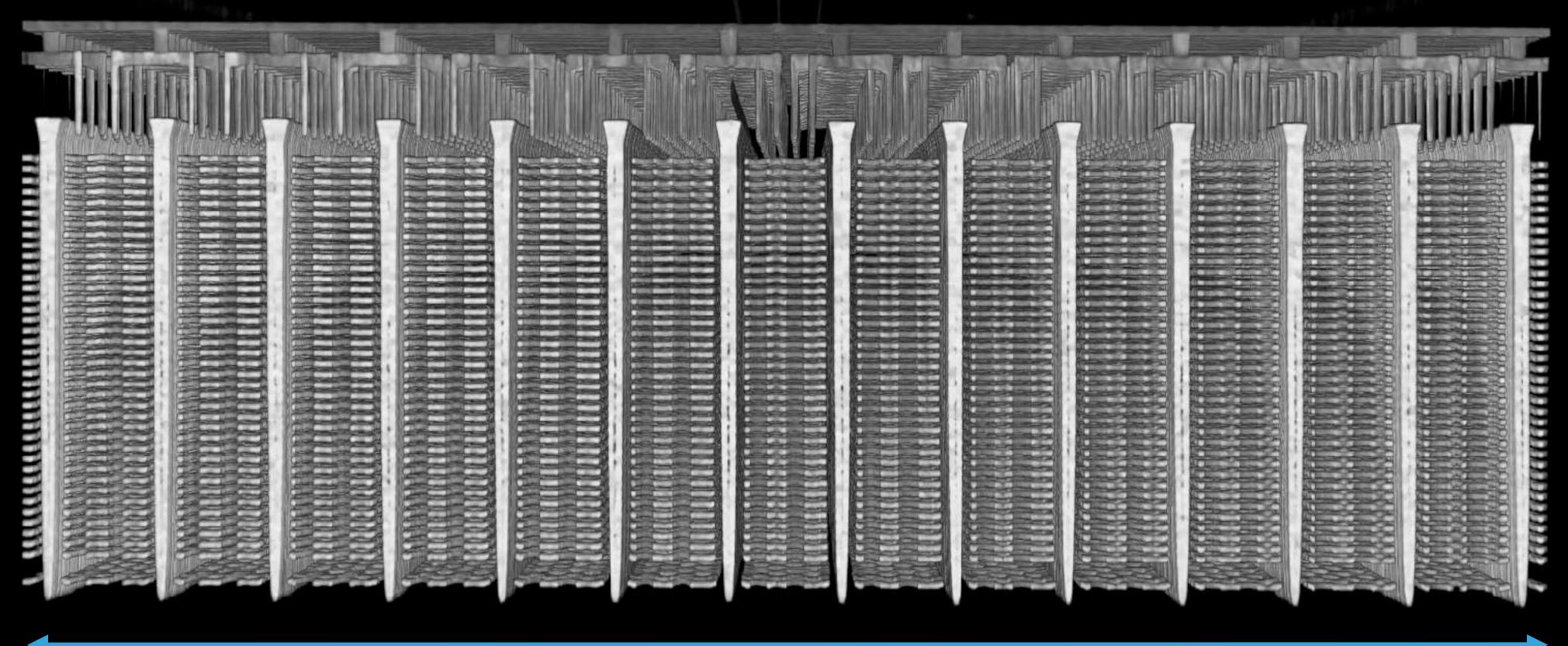
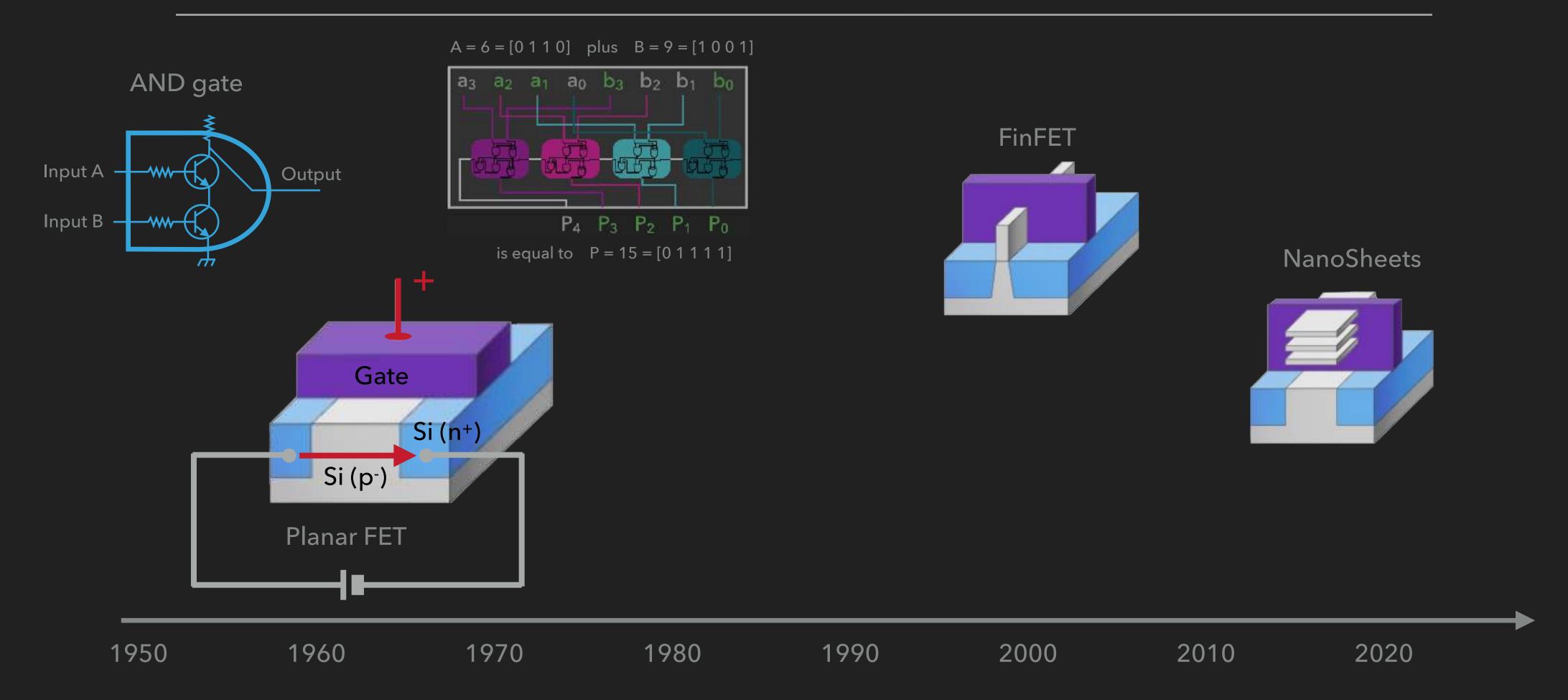


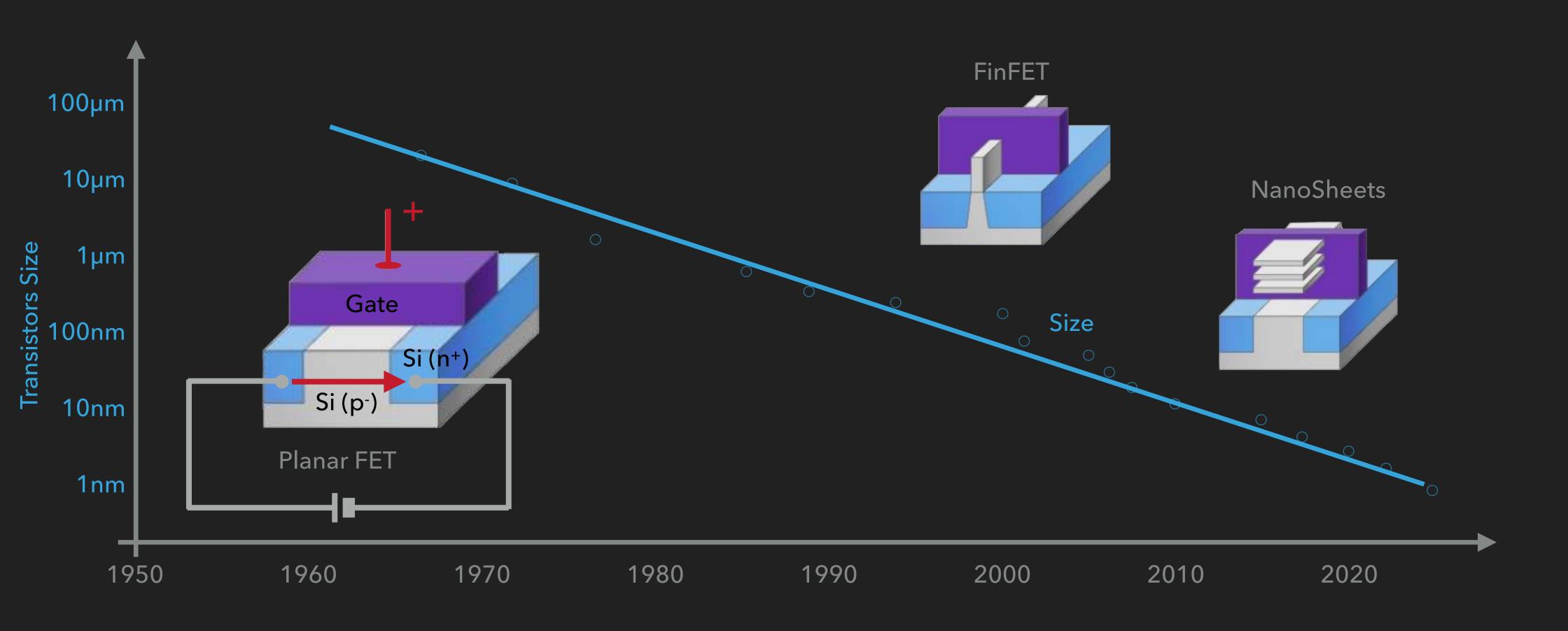
SAMSUNG V-NAND SSD, ELECTRON MICROSCOPY BY ZEISS CROSSBEAM (2015)

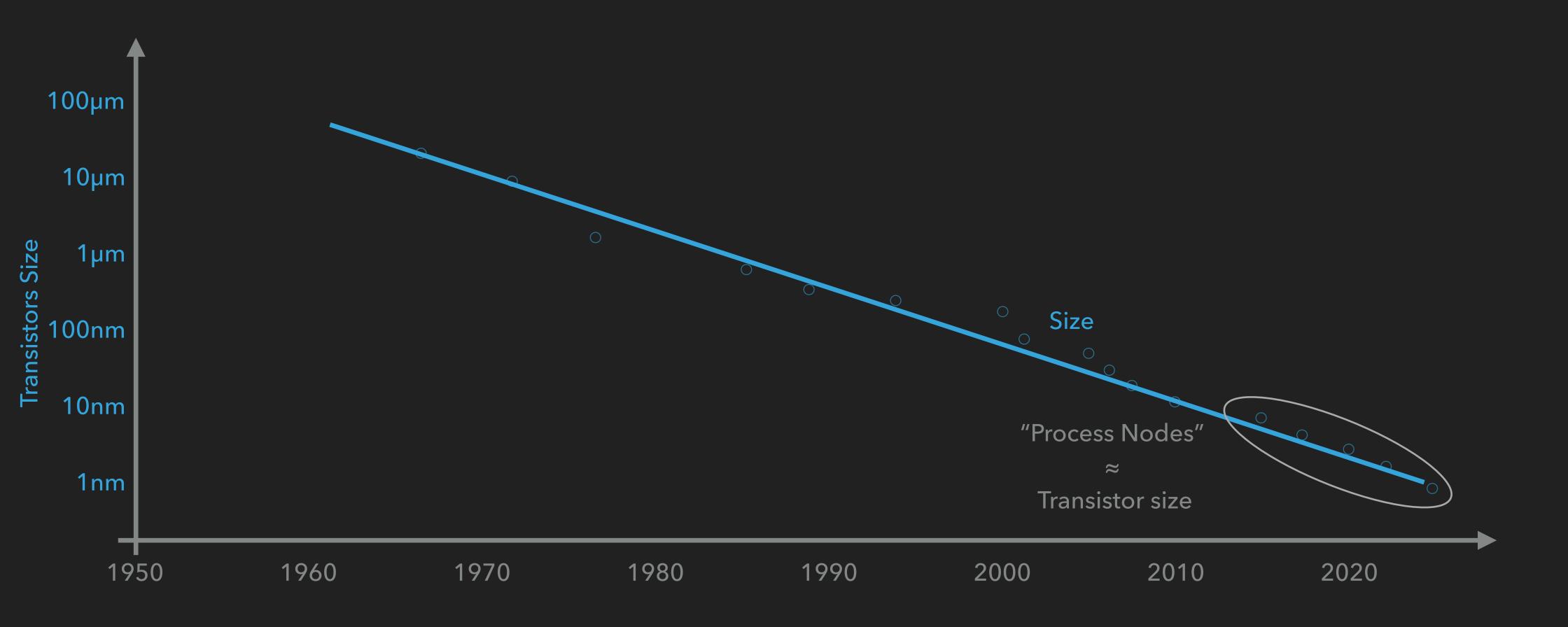


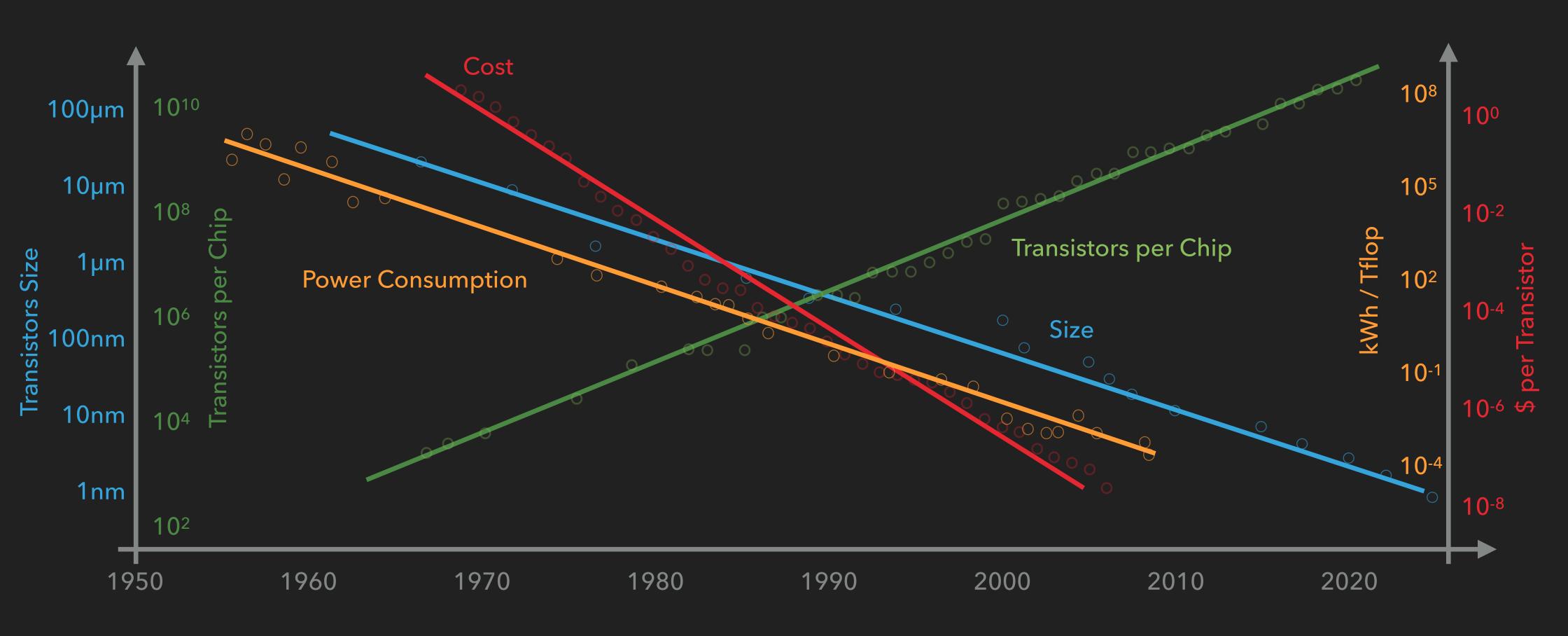
PRINCIPLES OF TRANSISTORS

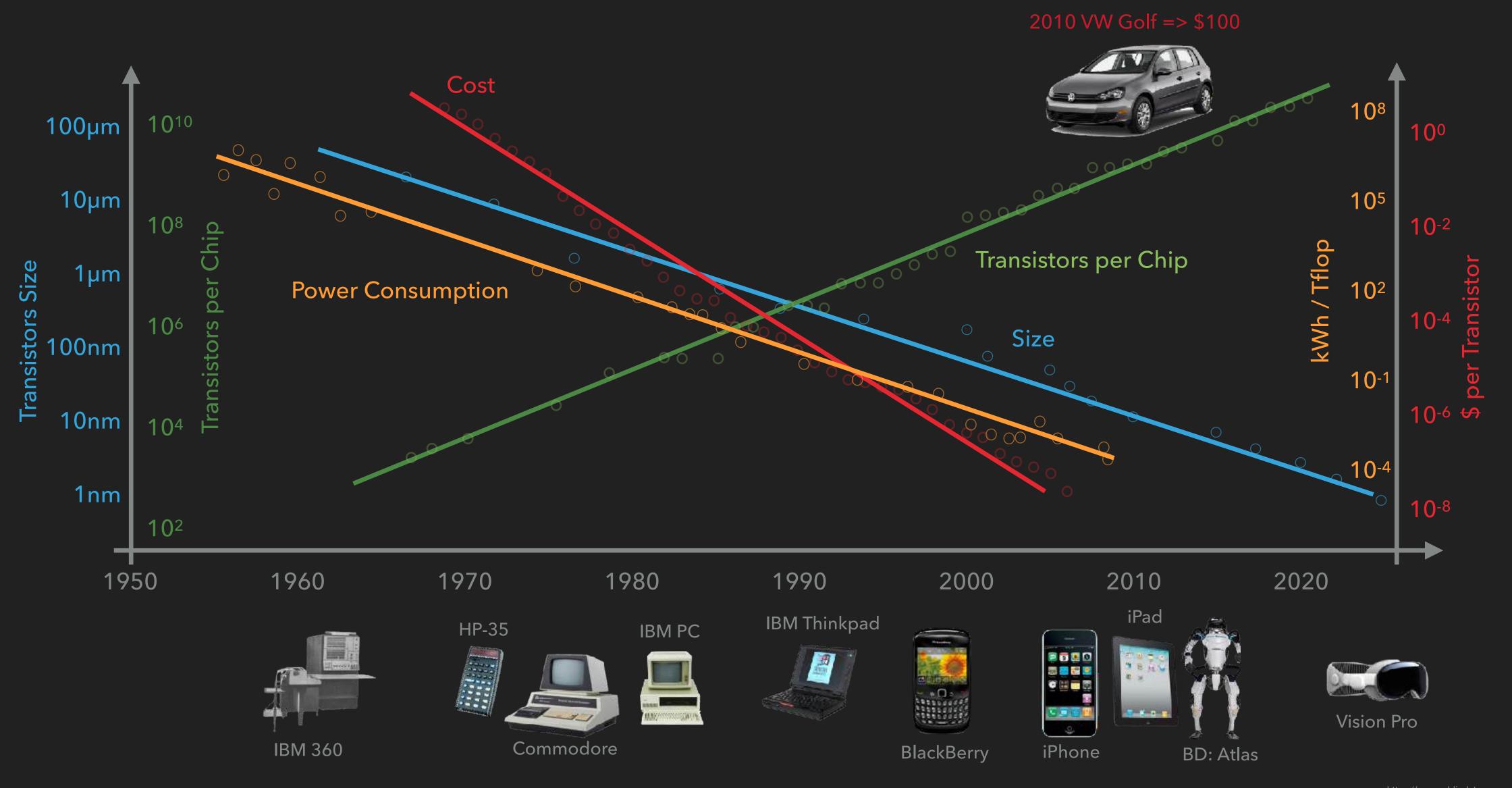


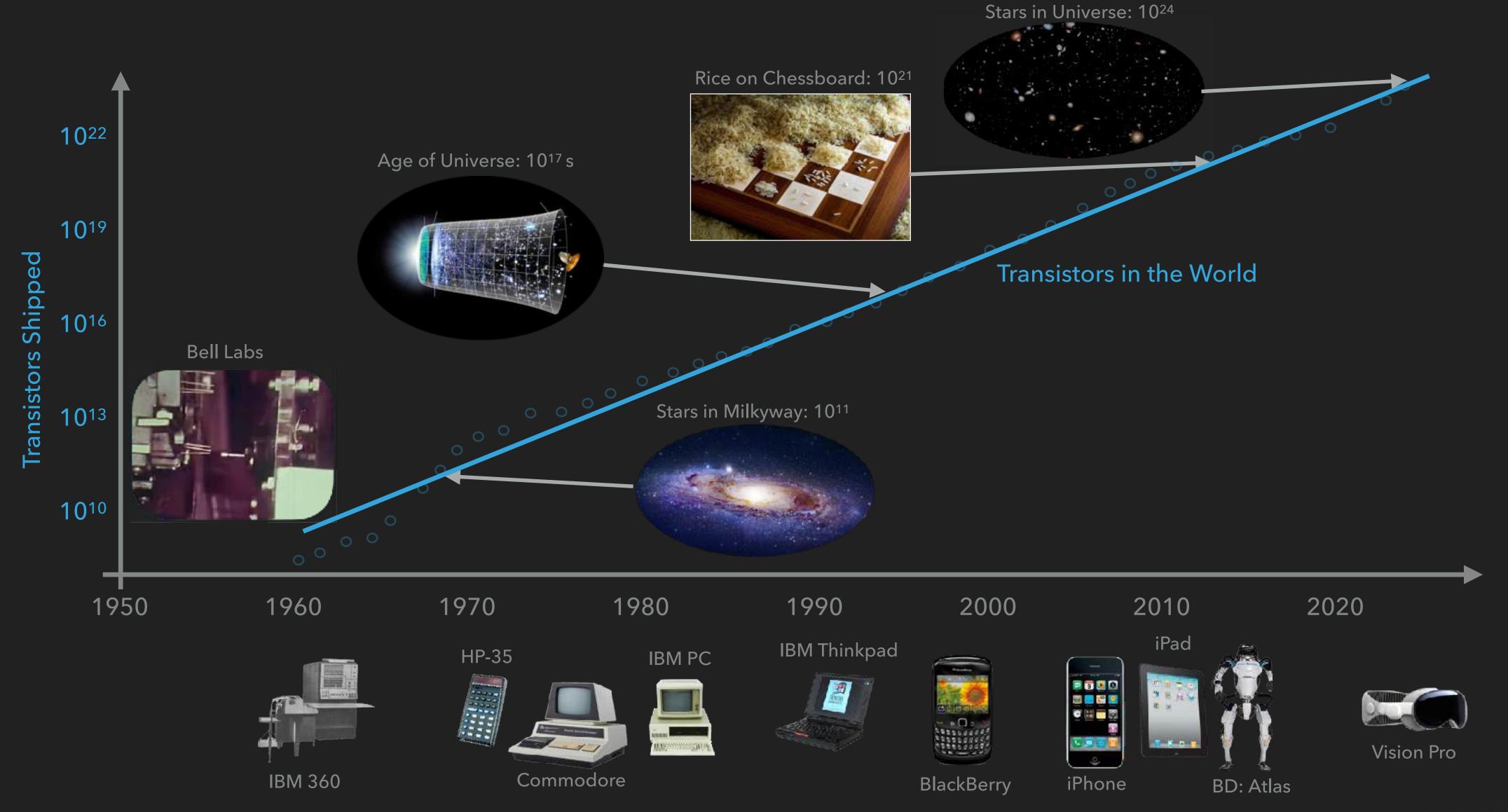
https://semiengineering.com/

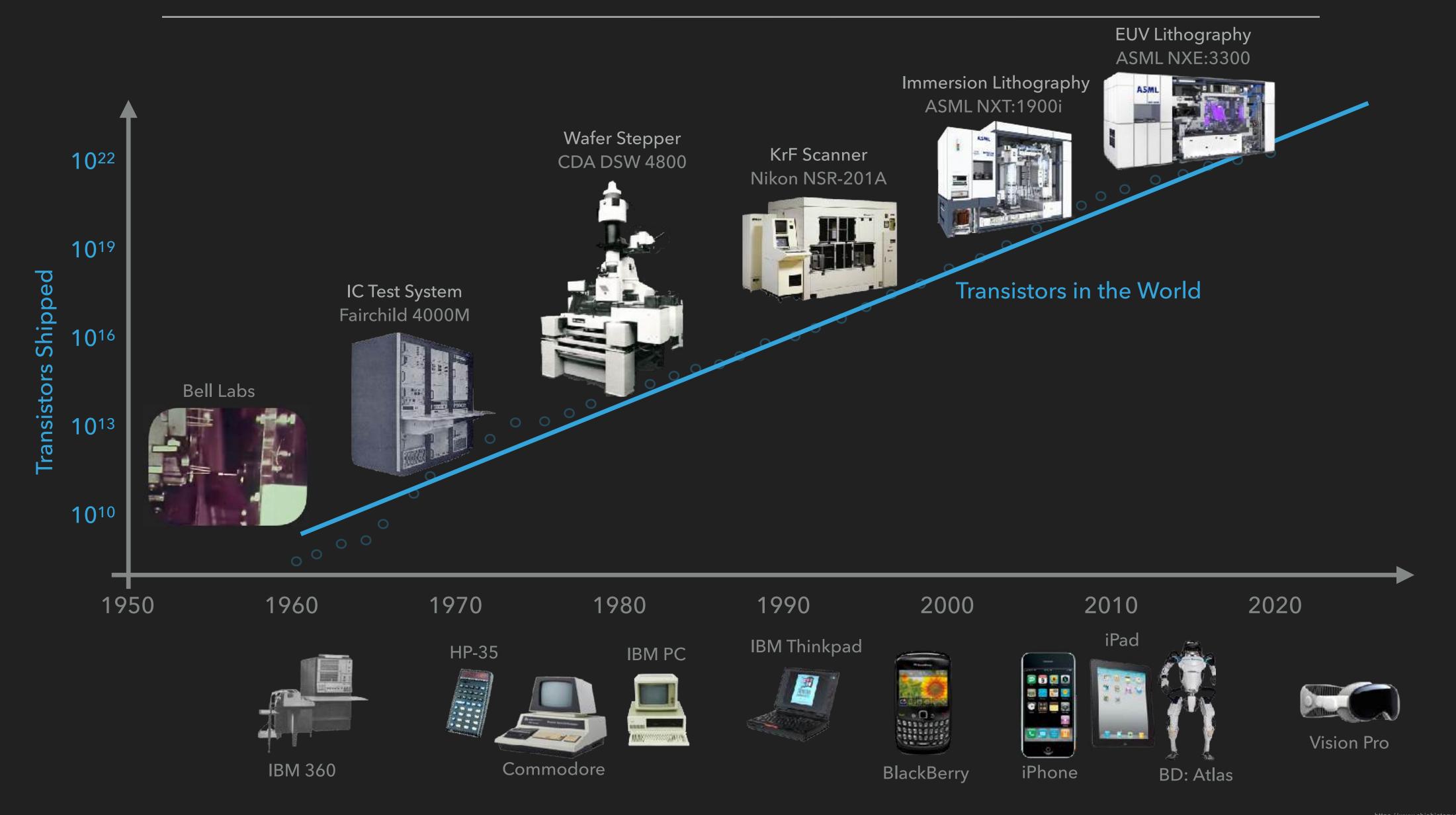


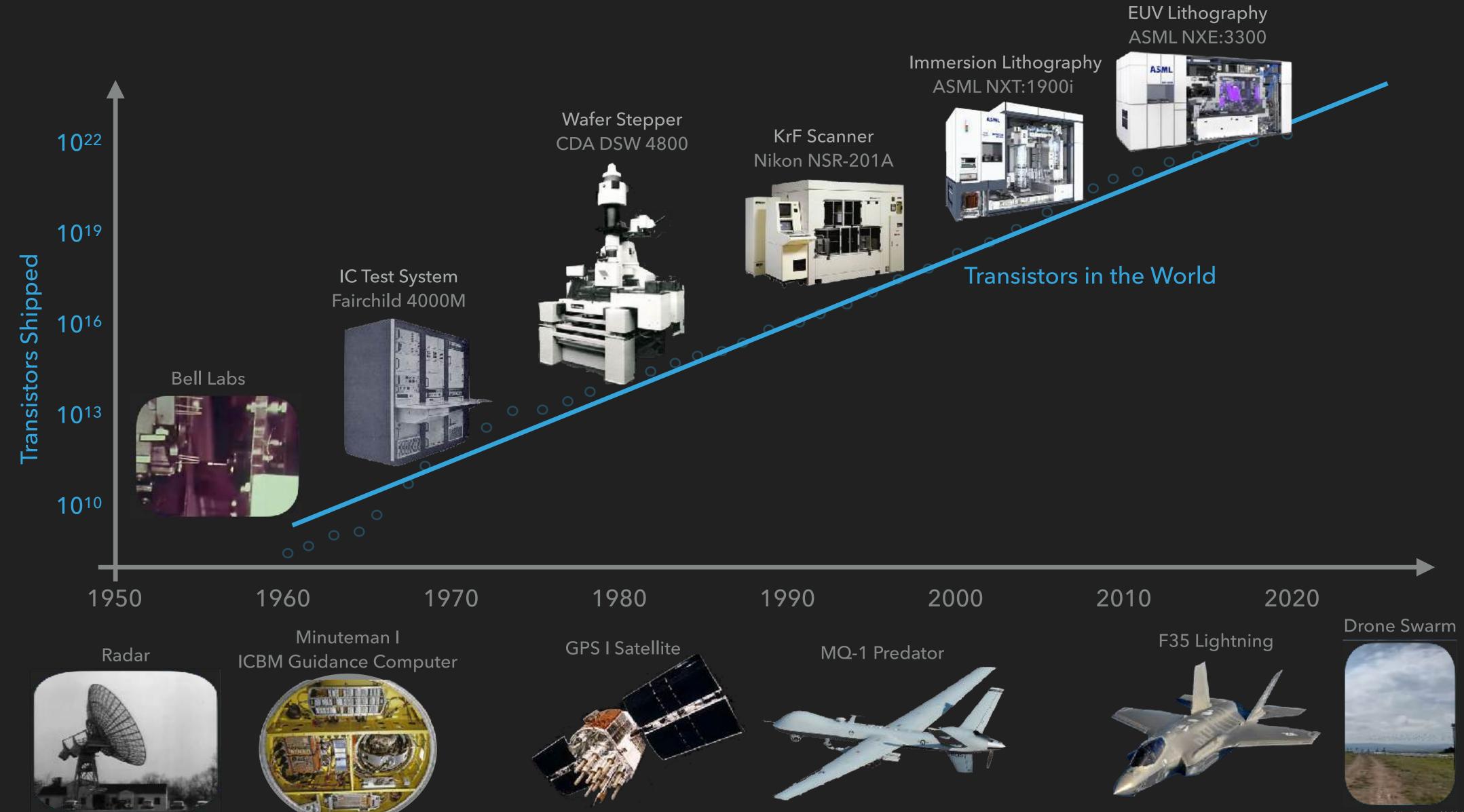


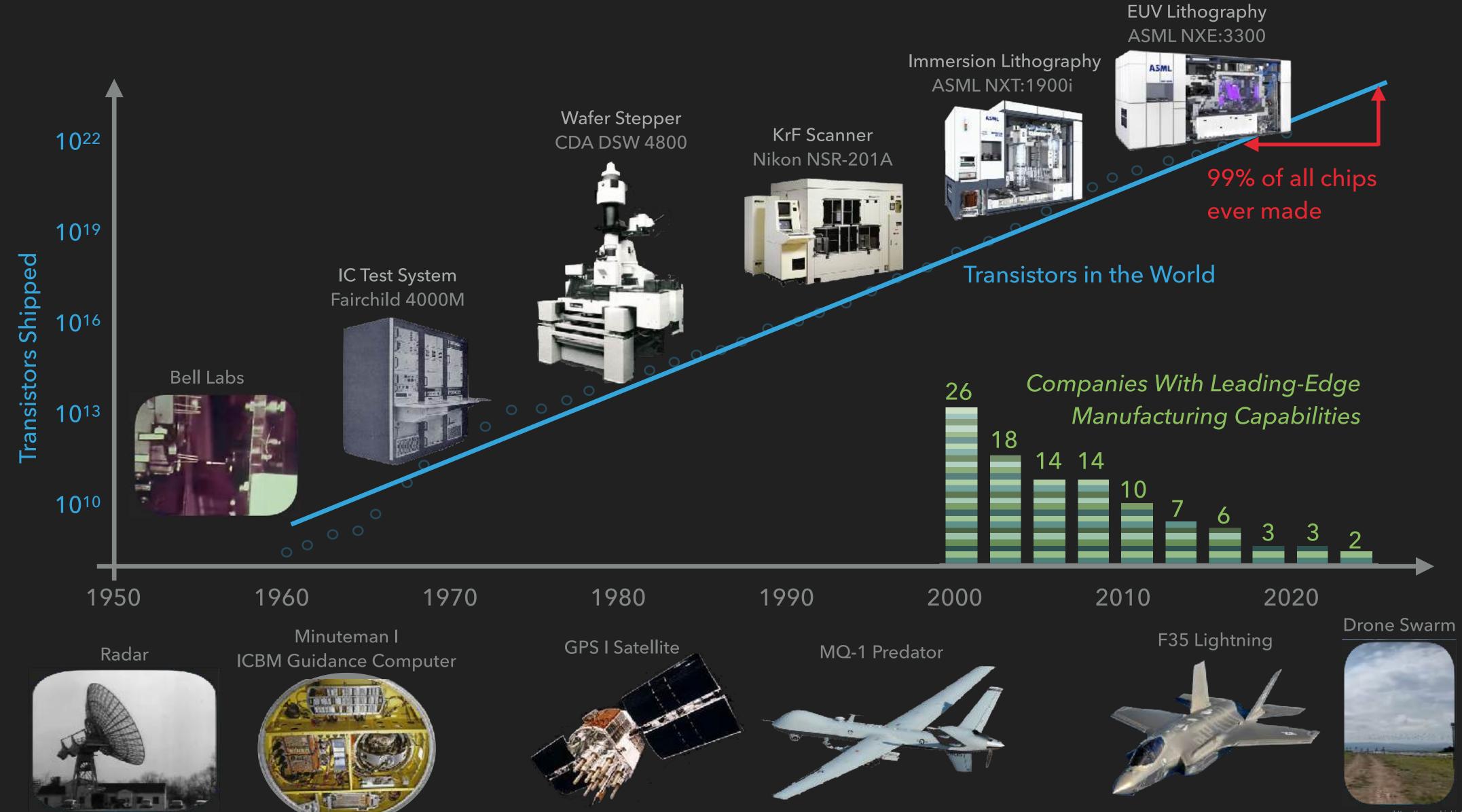












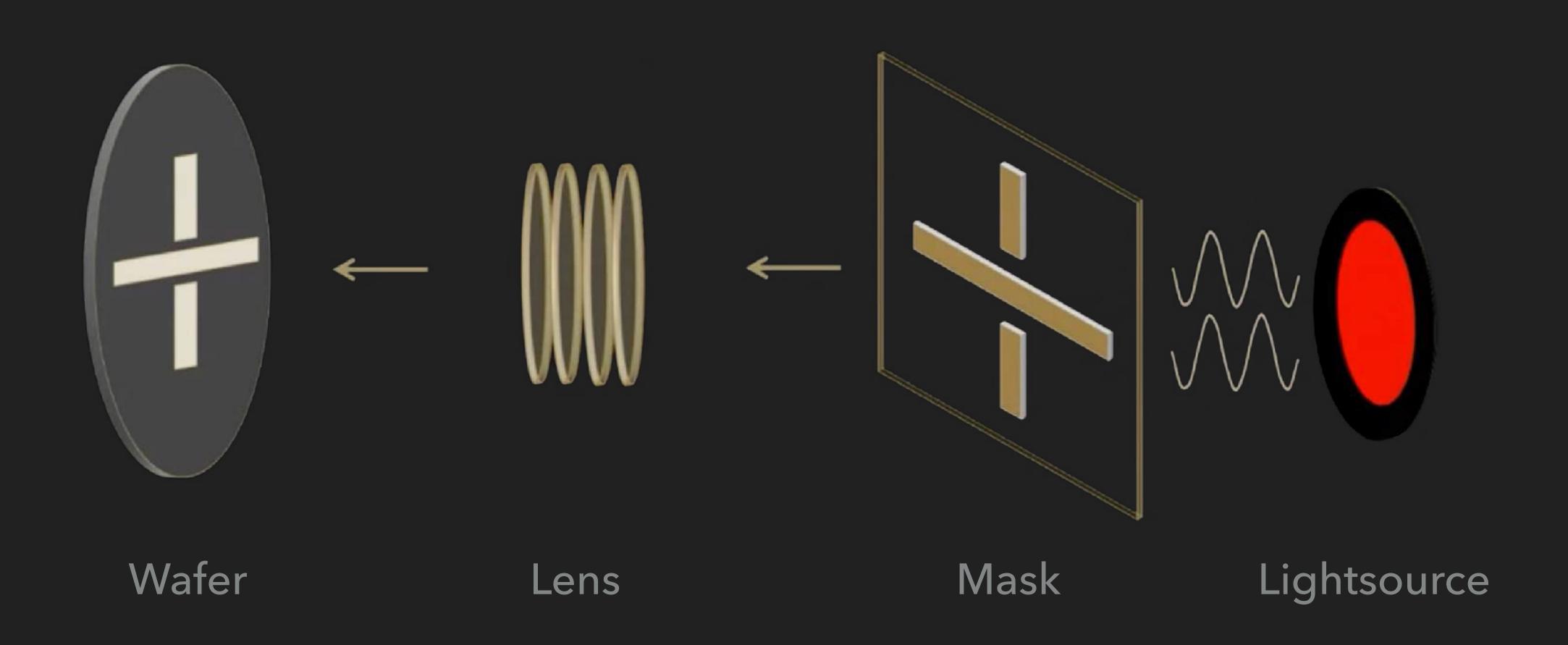
THE PRINTING PRESS - A REVOLUTION IN MASS PRODUCTION







PRINCIPLES OF PHOTOLITHOGRAPHY



Vivek Singh (NVIDIA): "Accelerating Computational Lithography" (GTC Spring 2023)

SILICON WAFER PRODUCTION

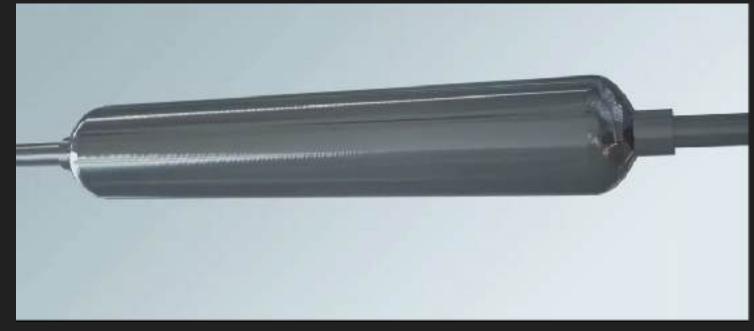
Ultra pure quartz mining



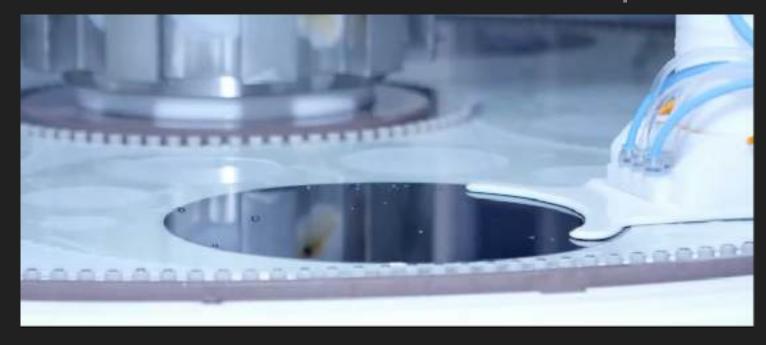
Silikon ingot crystal growing



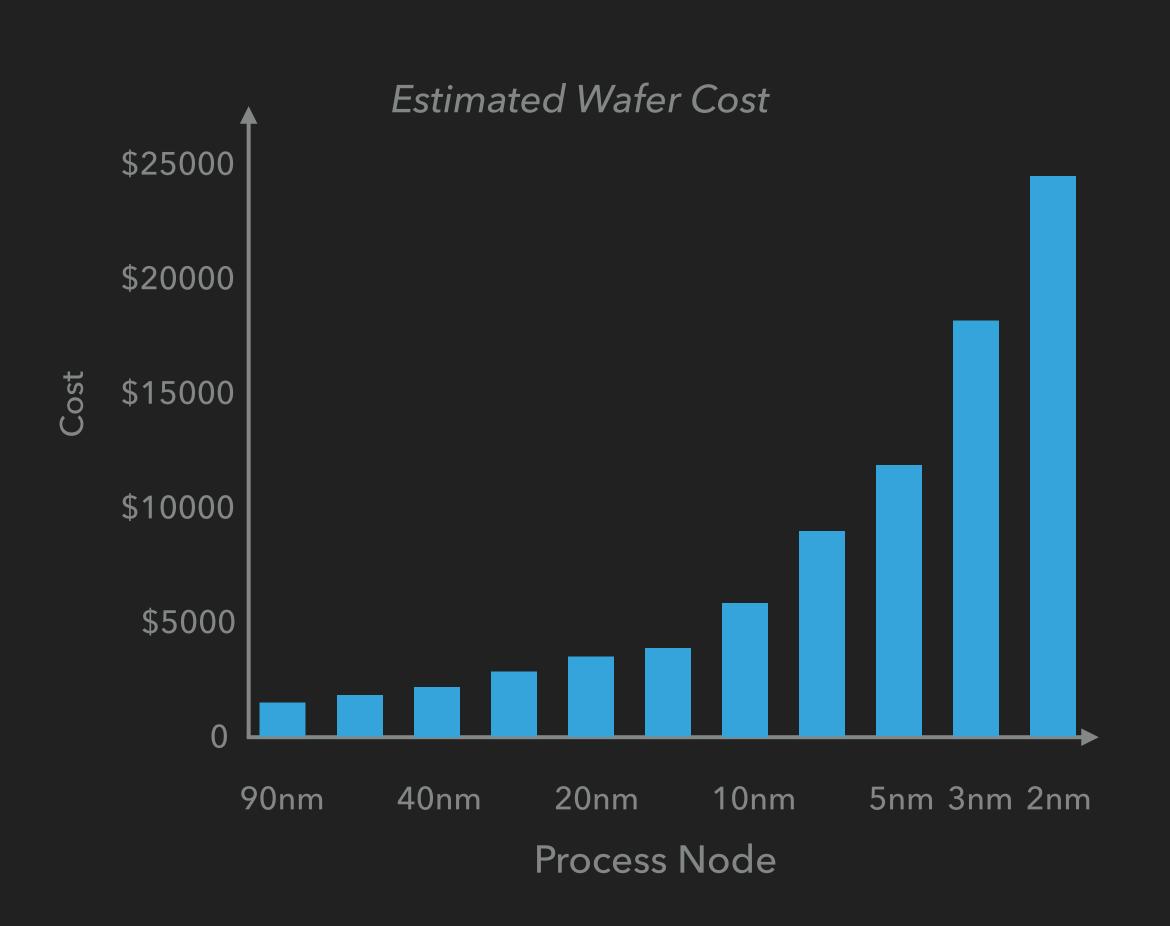
Ingot polishing and slicing



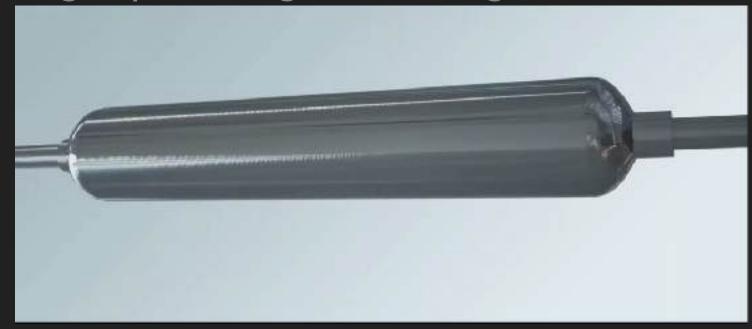
Wafer chemical and mechanical processing



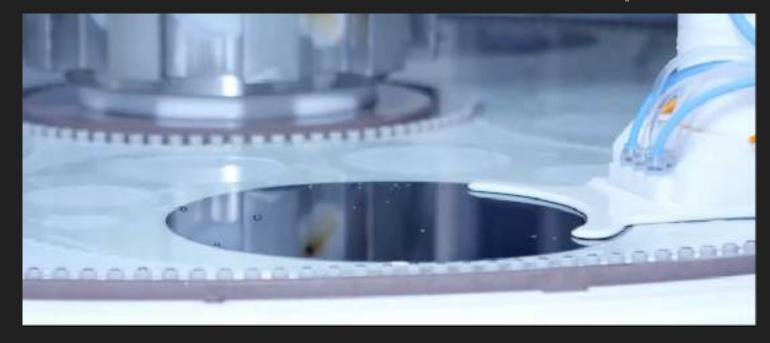
SILICON WAFER PRODUCTION



Ingot polishing and slicing



Wafer chemical and mechanical processing





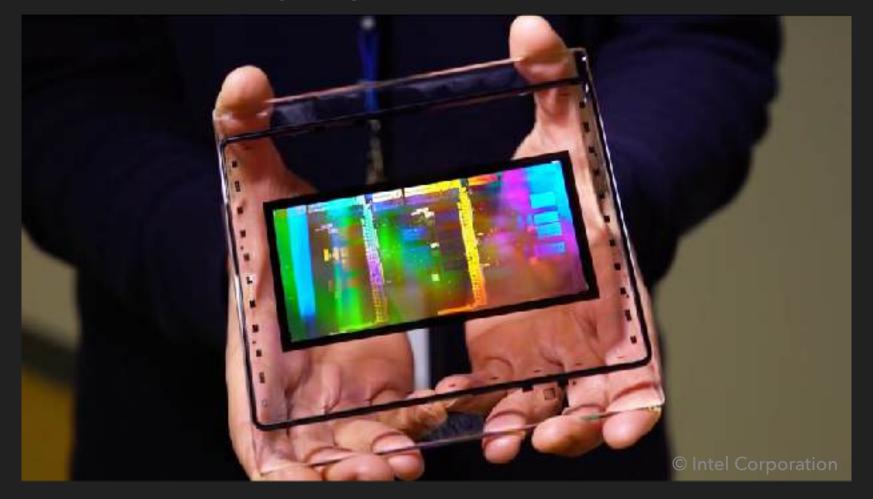
PHOTOMASK

- Electron beam printing
- Zero defects
- $X: 33 \text{mm}/13 \text{nm} = 2.5 \times 10^6 \text{ pixel}$
- Y: $26 \text{mm} / 13 \text{nm} = 2 \times 10^6 \text{ pixel}$
- 5T Pixel Screen

How it started...



...and how it's going.



PHOTOMASK

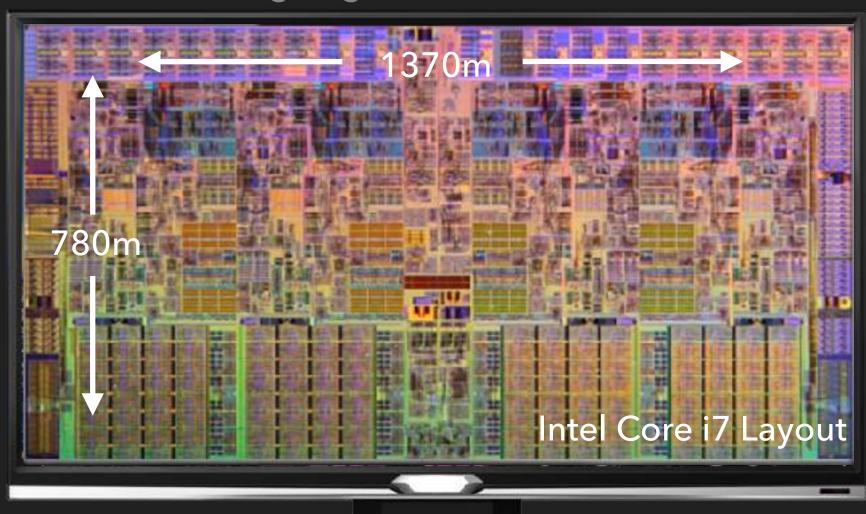
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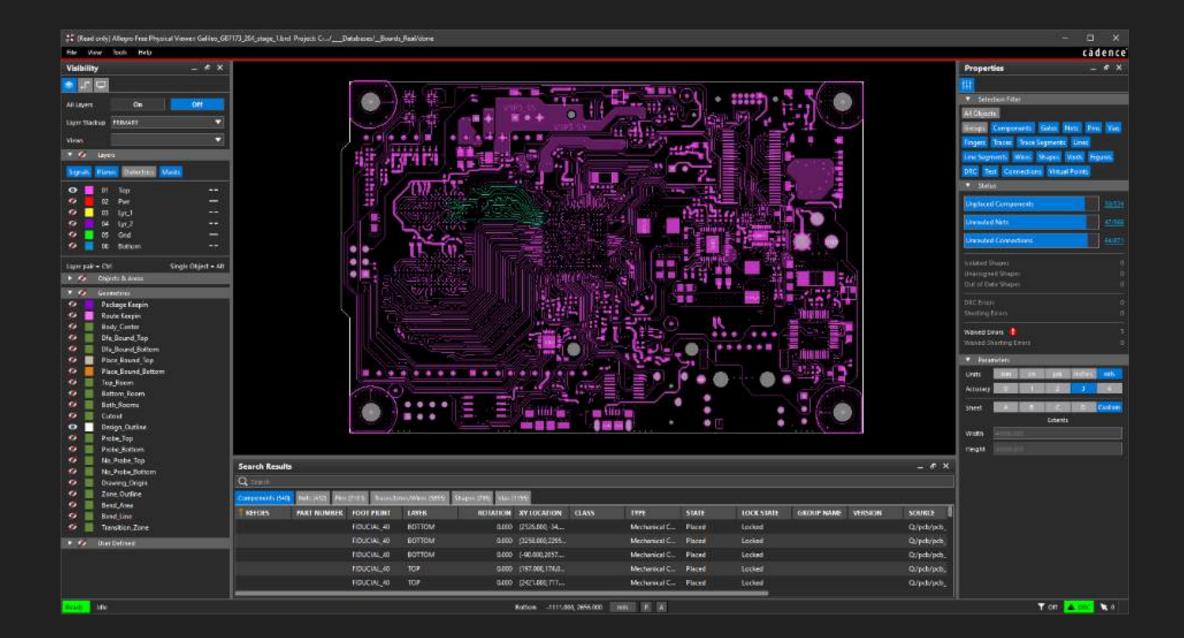
...and how it's going.



HDTV

ELECTRONIC DESIGN AUTOMATION

- NVIDIA 'Hopper': 80B Transistors
- Designed in about 2 years
- '100M transistors per day'
- ▶ 1-Layer Photomask File: 150GB
- About 100 Layers in latest 3nm Process



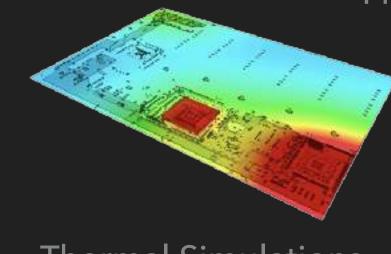
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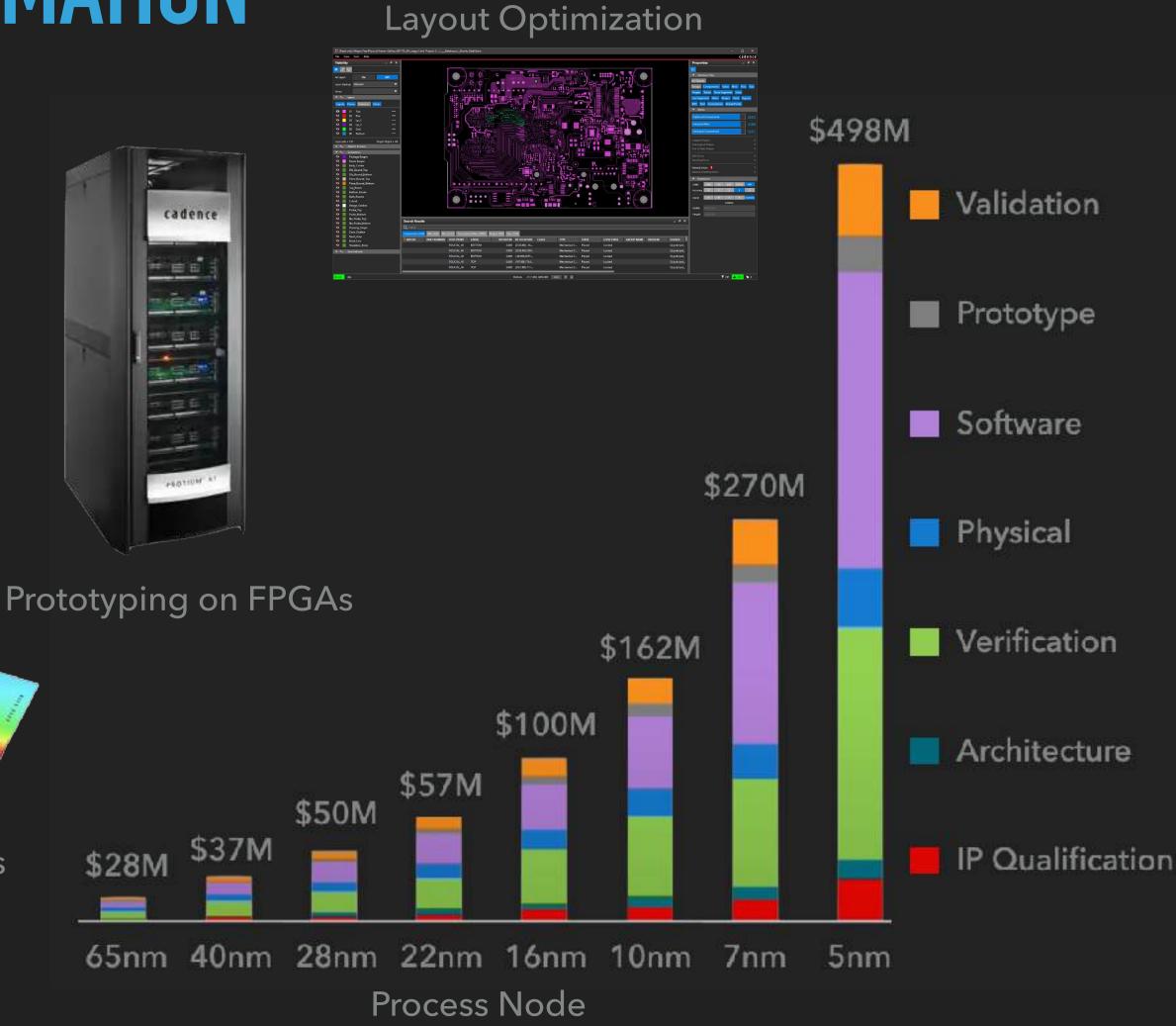
≈100% market share



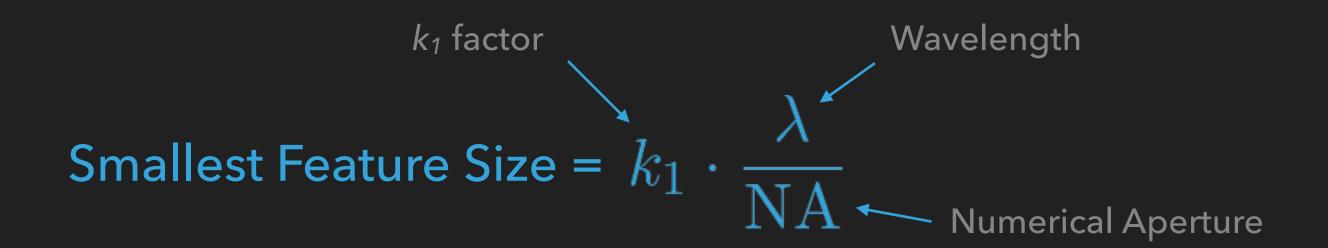


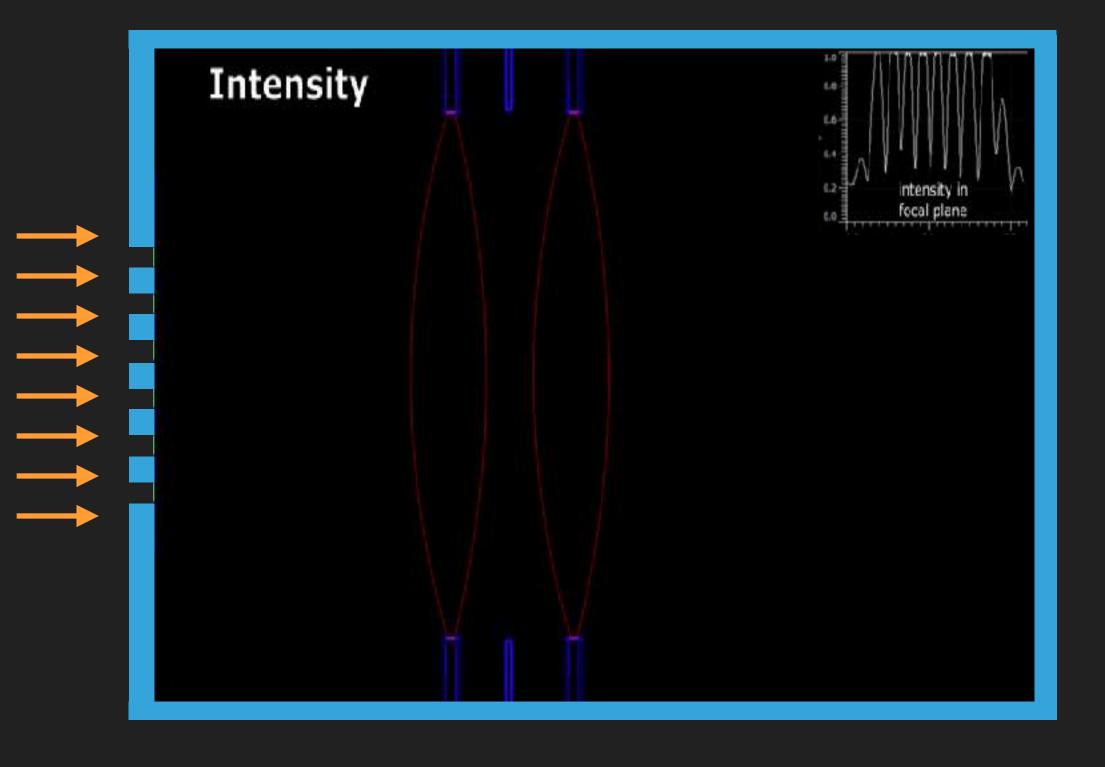
cadence

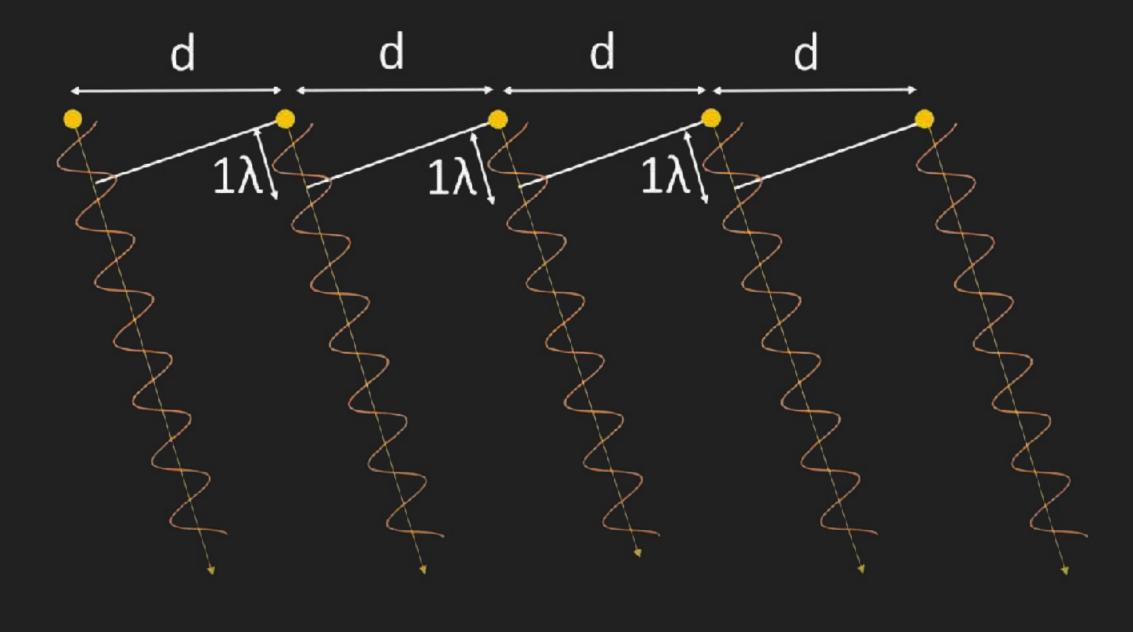
Thermal Simulations



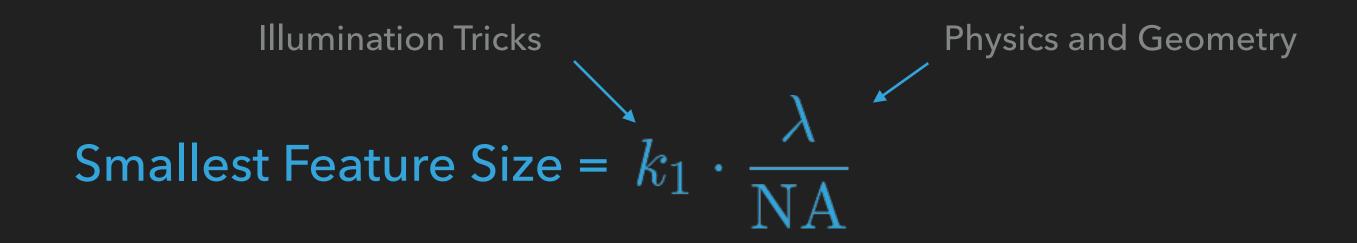
DIFFRACTION

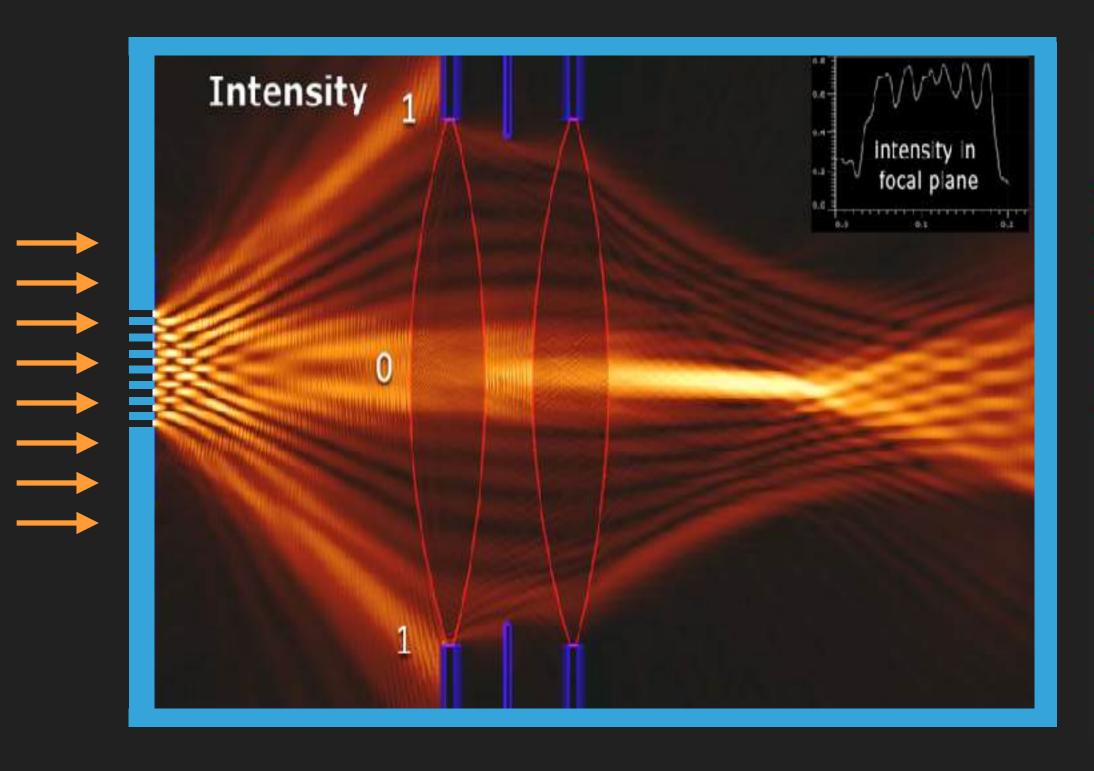


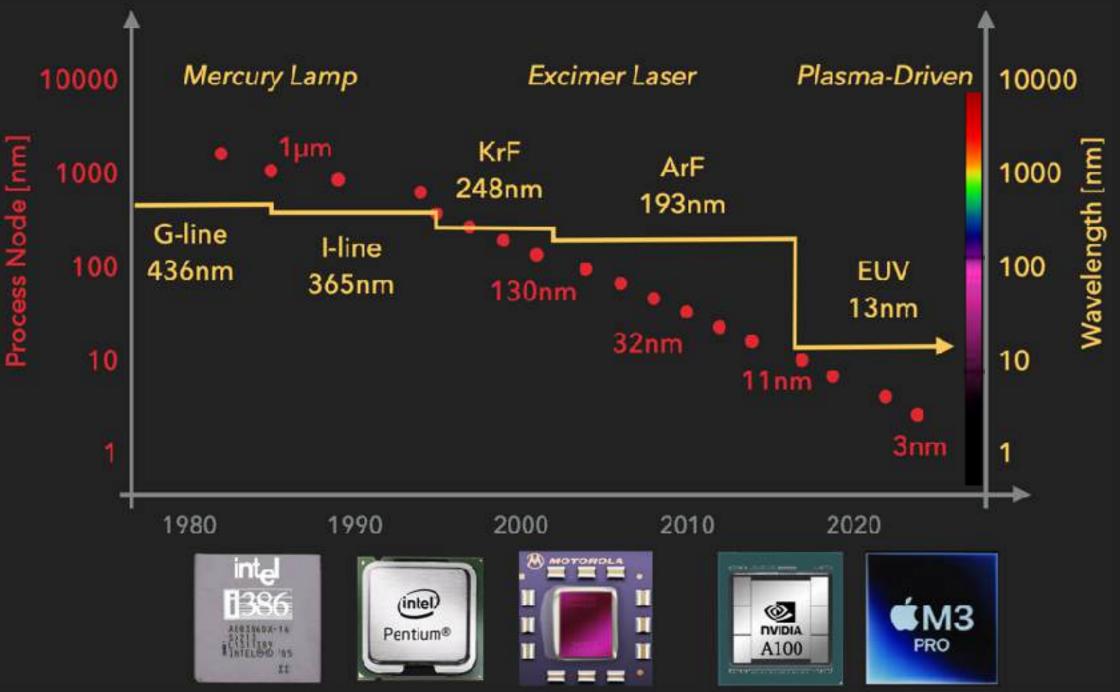




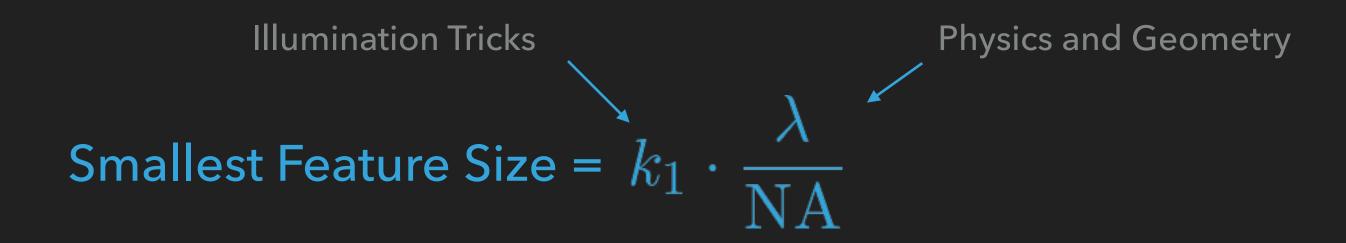
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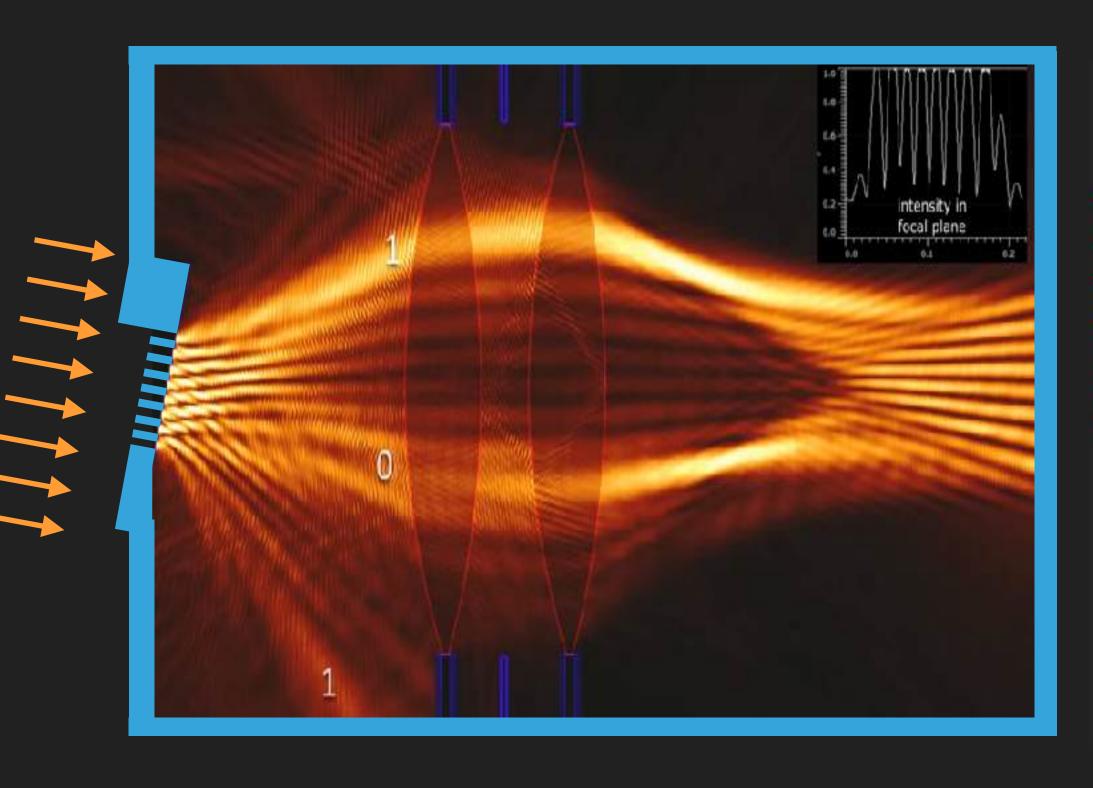


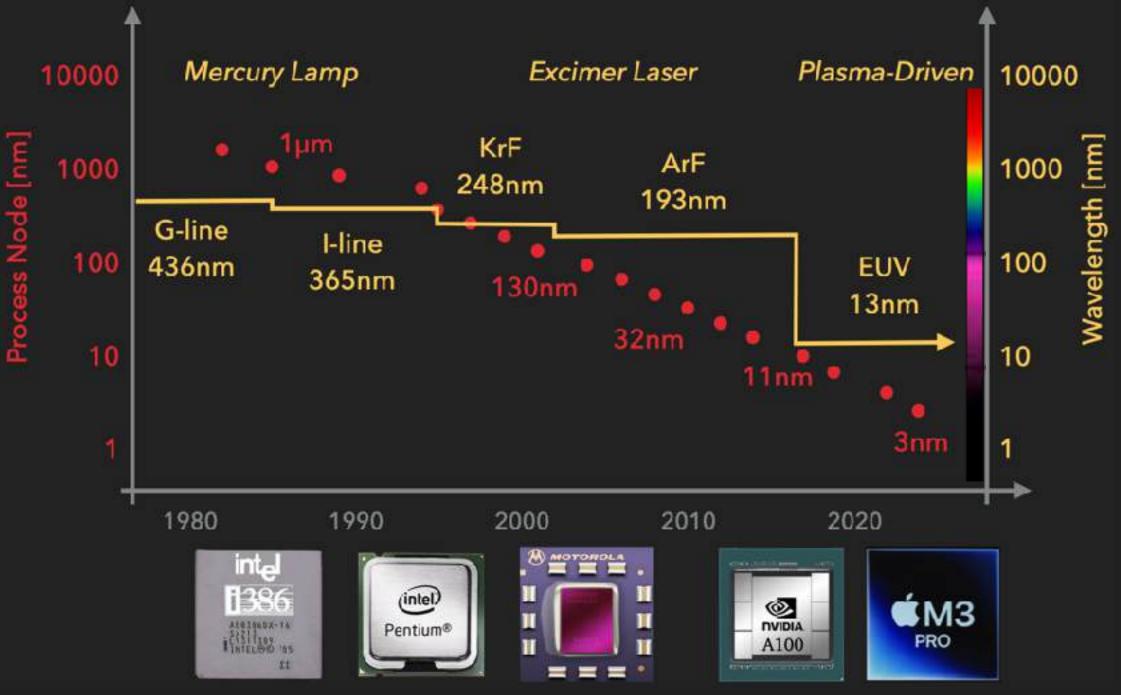




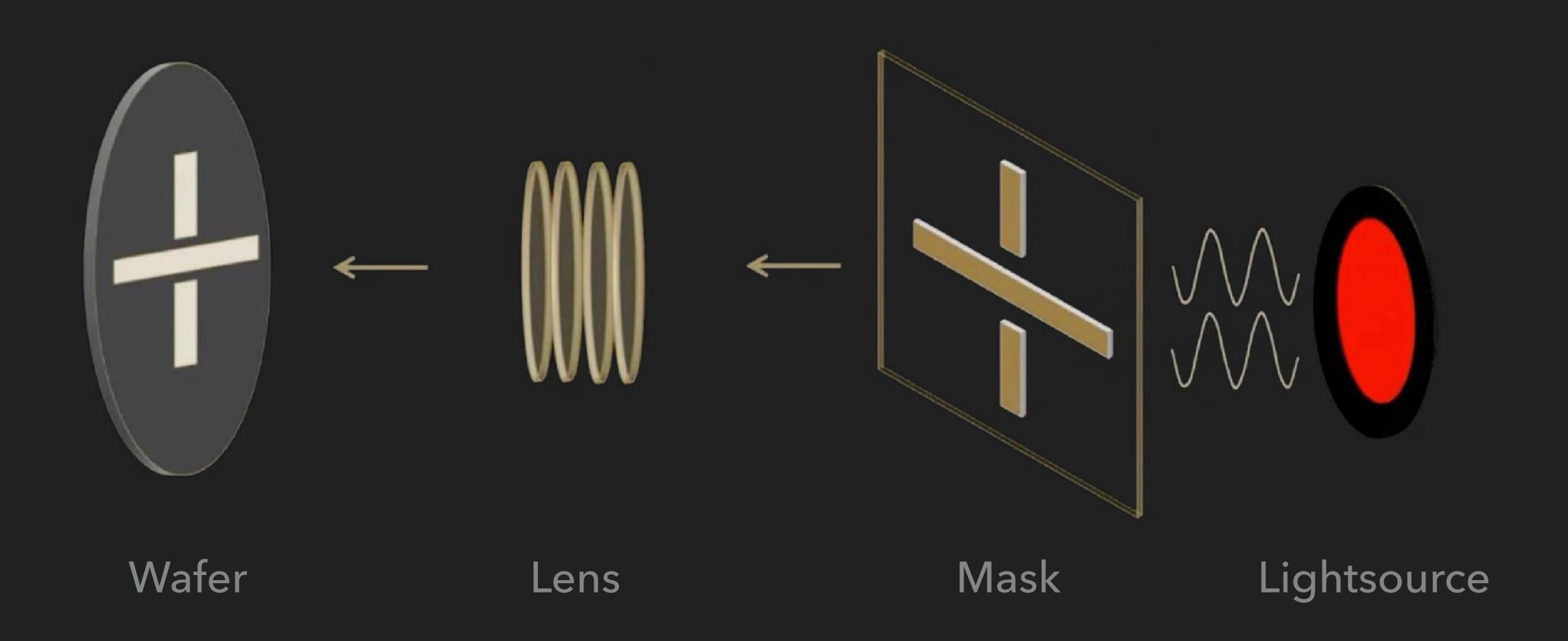
DIFFRACTION



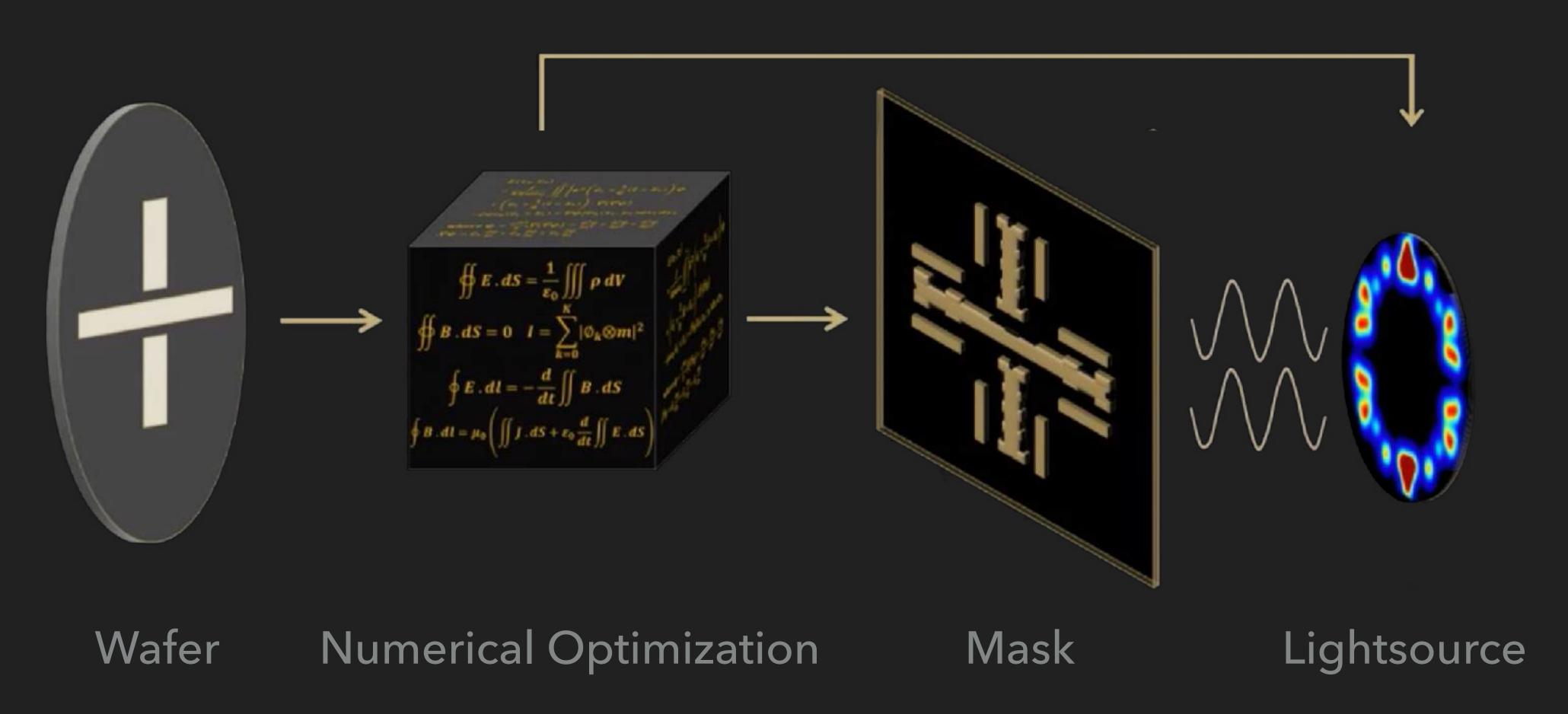




PRINCIPLES OF PHOTOLITHOGRAPHY

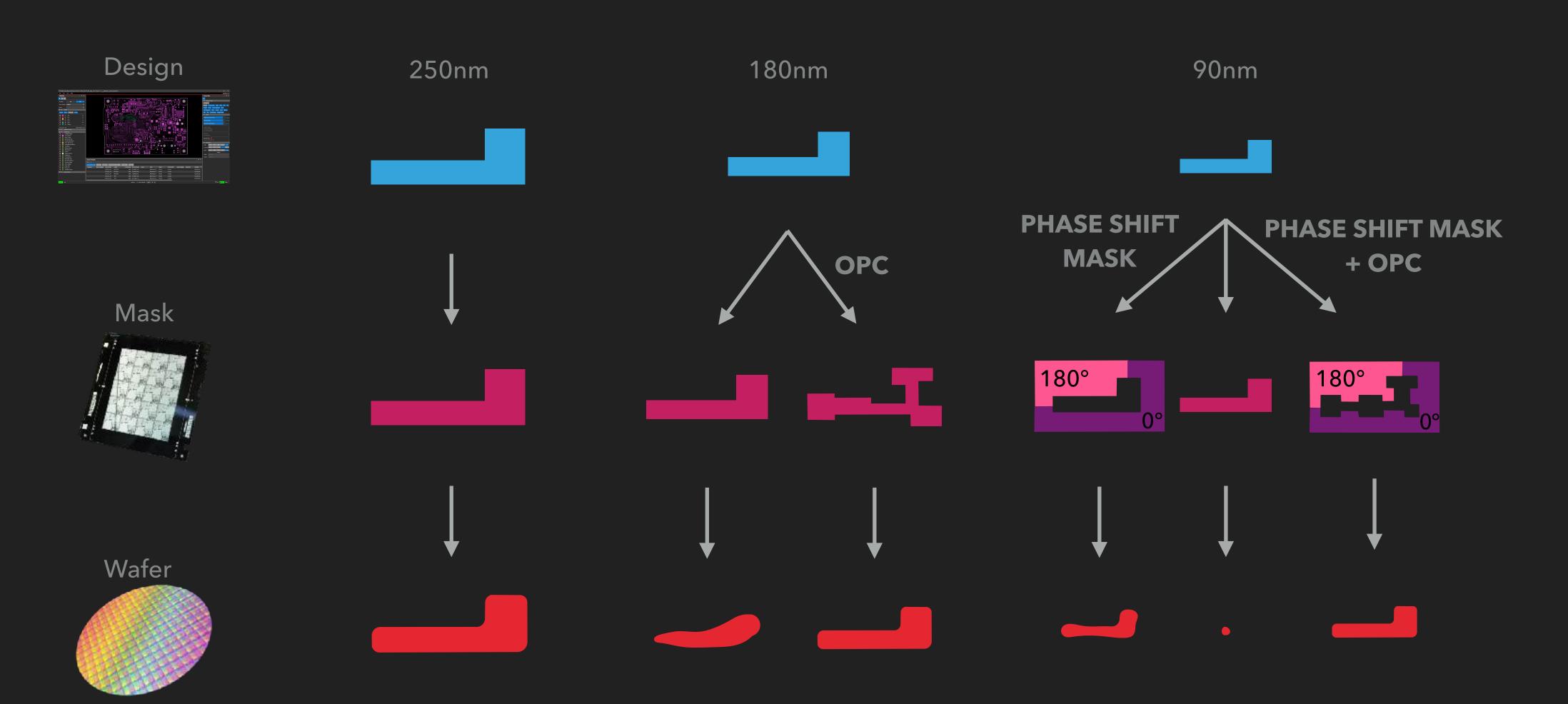


COMPUTATIONAL LITHOGRAPHY

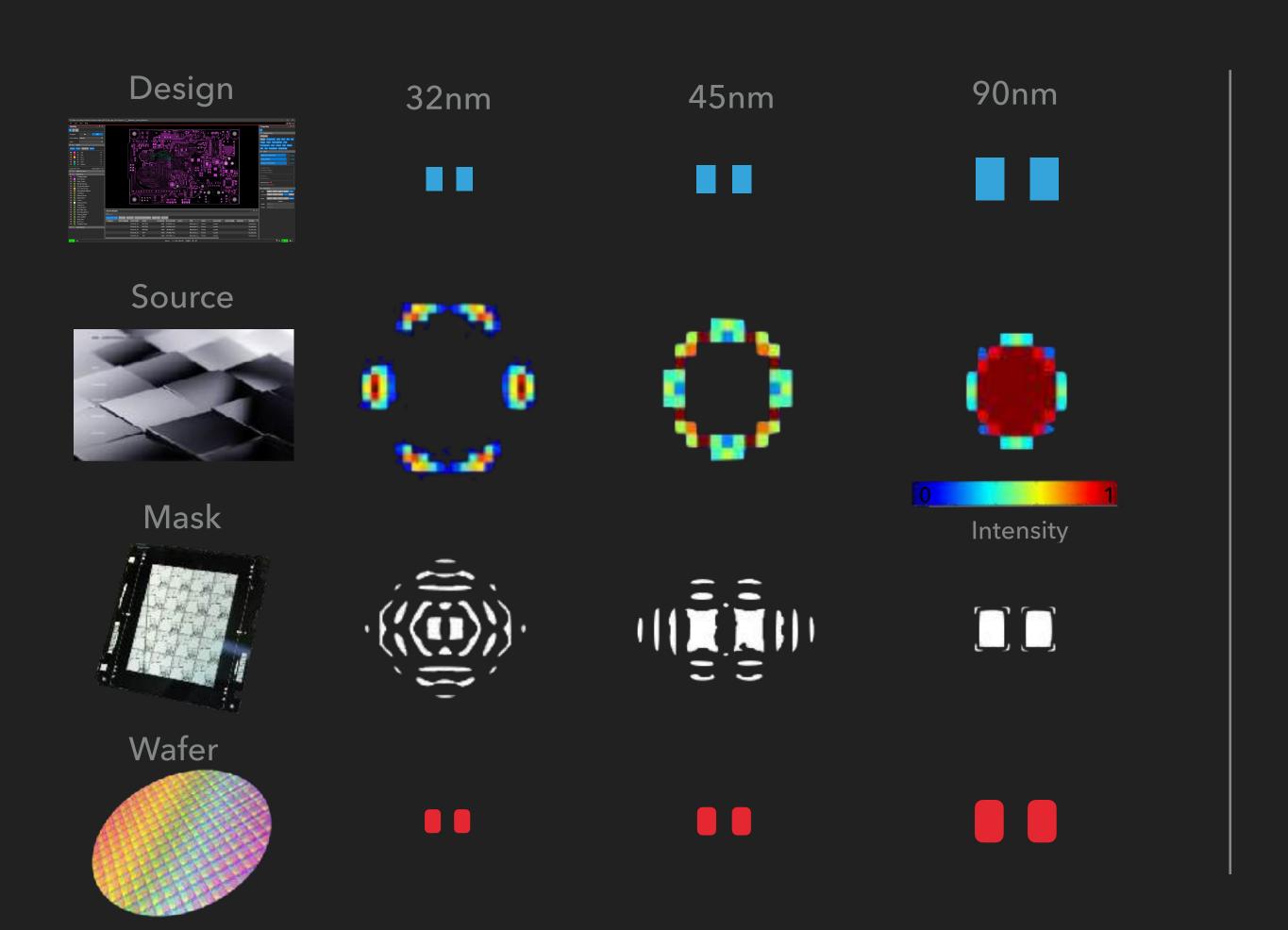


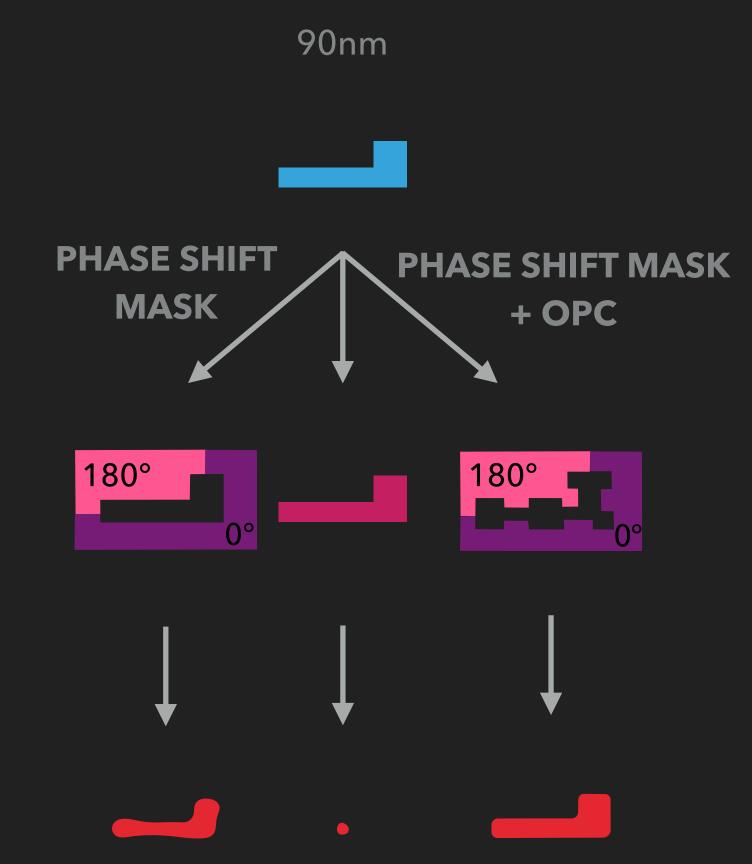
Vivek Singh (NVIDIA): "Accelerating Computational Lithography" (GTC Spring 2023)

OPTICAL PROXIMITY CORRECTION

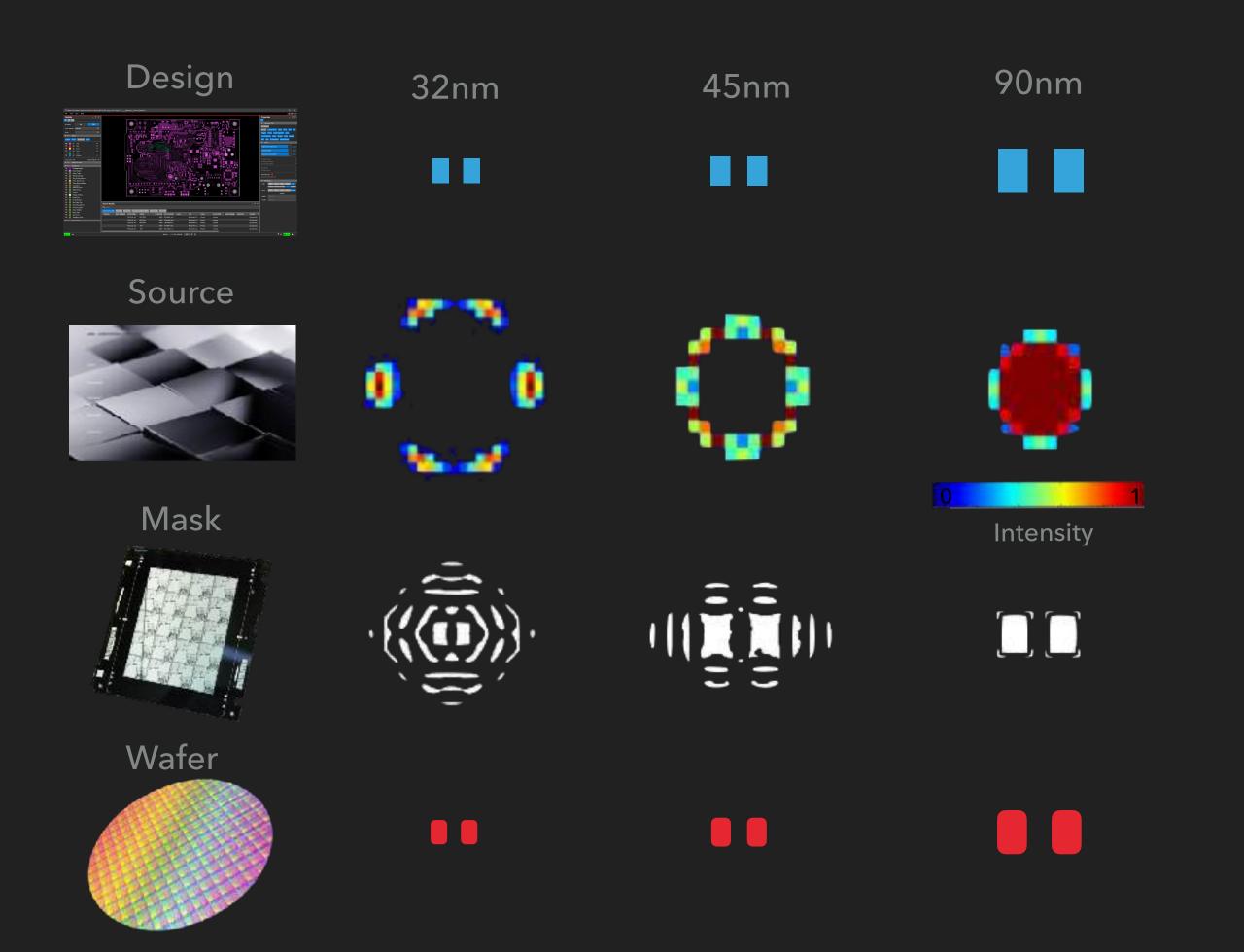


OPTICAL PROXIMITY CORRECTION & SOURCE-MASK OPTIMIZATION



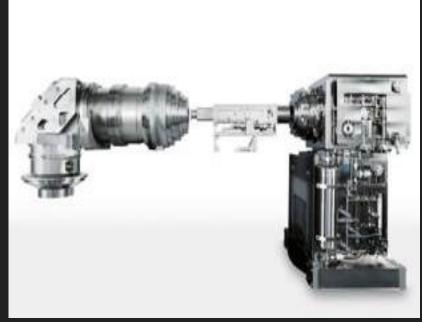


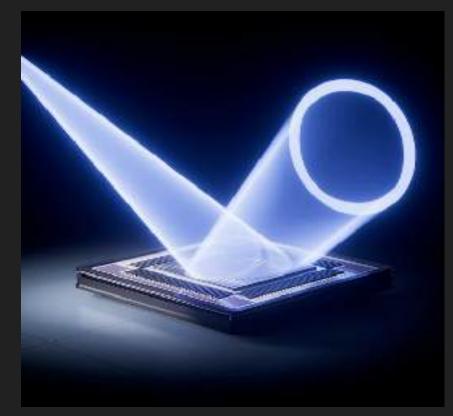
OPTICAL PROXIMITY CORRECTION & SOURCE-MASK OPTIMIZATION



ASML TwinScan NXT:1980Di

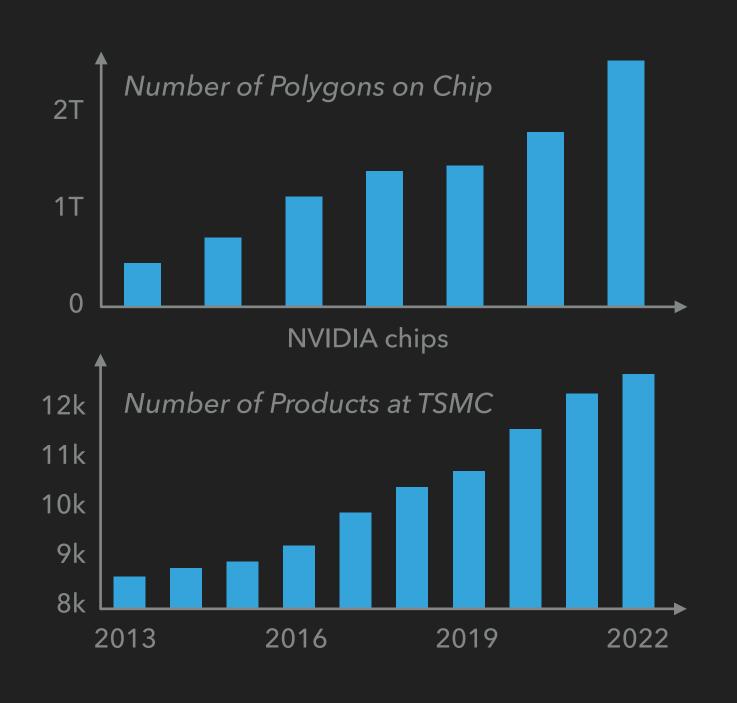


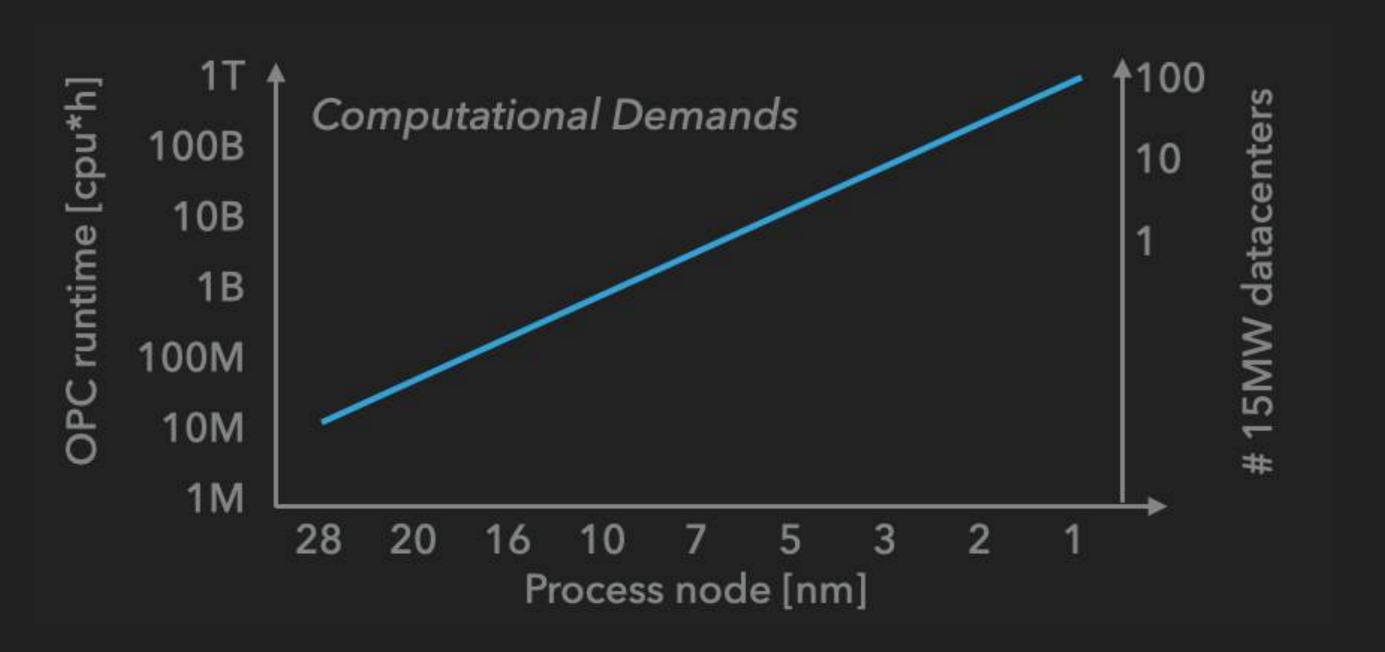




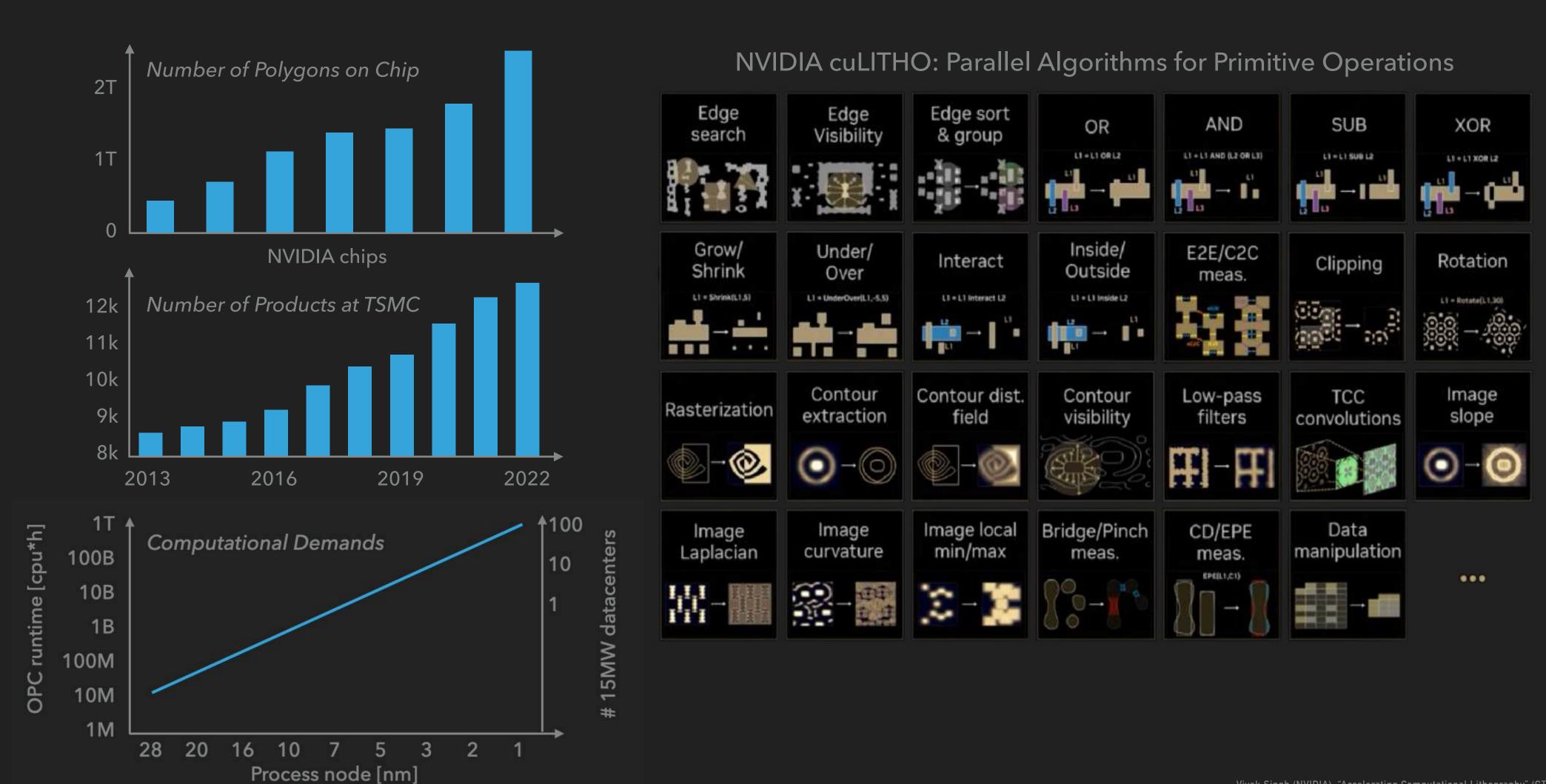


COMPUTATIONAL DEMANDS IN CHIP DESIGN

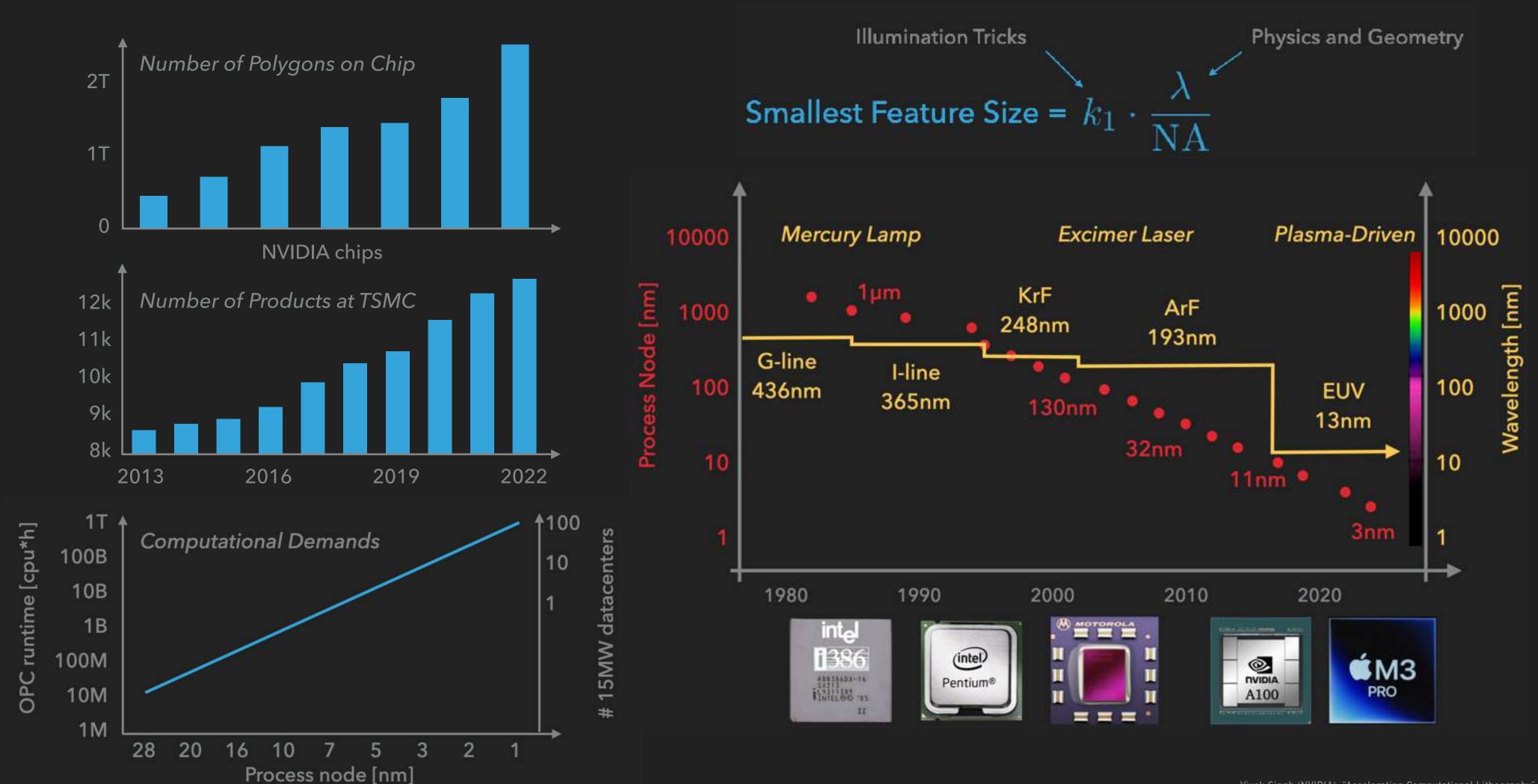




COMPUTATIONAL DEMANDS IN CHIP DESIGN

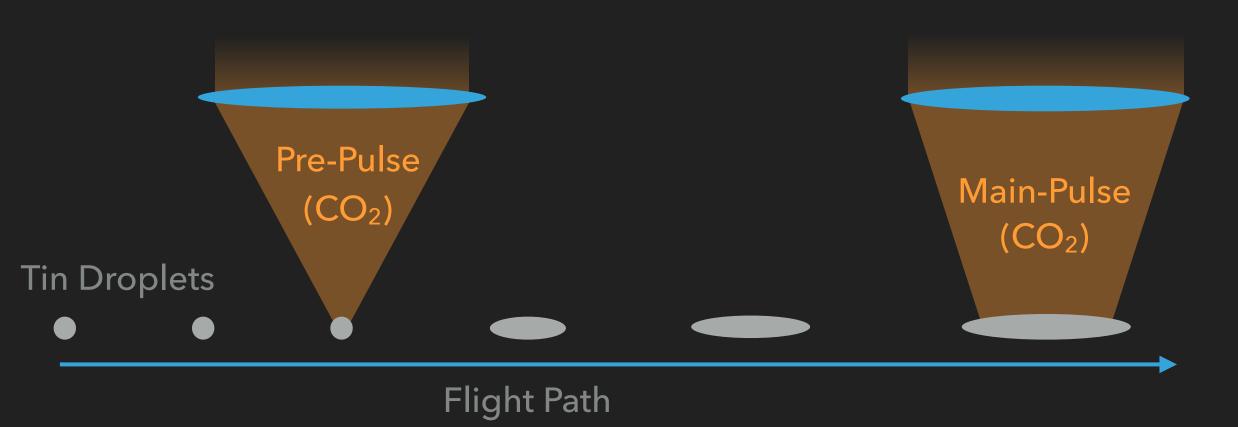


COMPUTATIONAL DEMANDS IN CHIP DESIGN



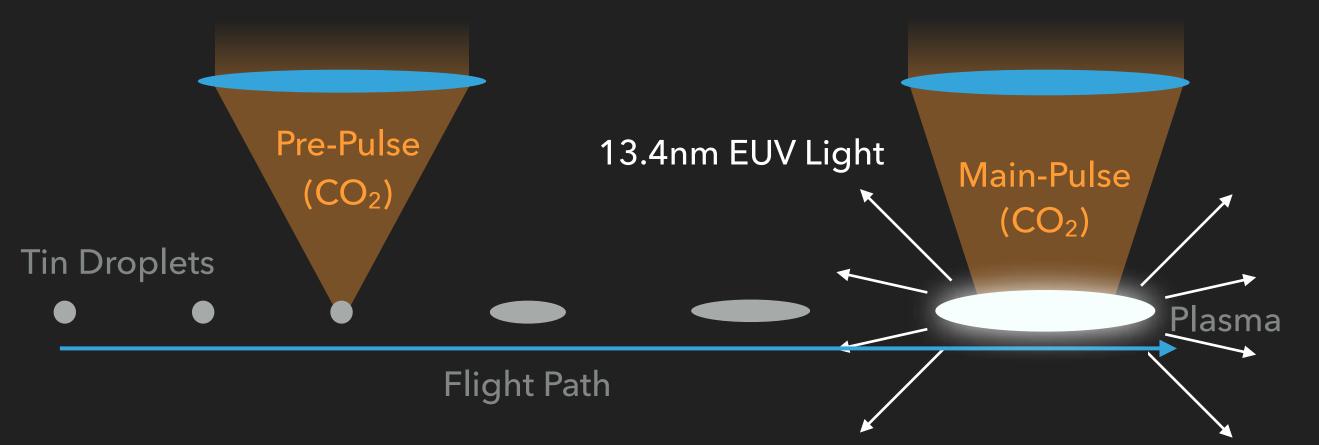
THE EUV LIGHT SOURCE

- Droplet Size: 27 μm
- Droplet Frequency: 50kHz
- Droplet Speed: 280km/h
- Droplet Distance: 1.6mm
- ▶ CO2 Drive Laser Power: 30kW



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SemiSlides: "ASML EUV Light Source" (https://www.youtube.com/watch?v=LnsuCp1xt3w)

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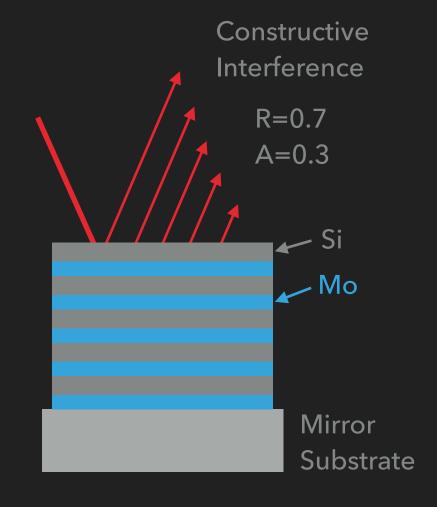




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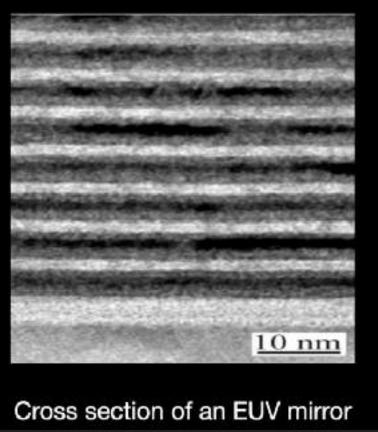
EUV MIRRORS BY ZEISS

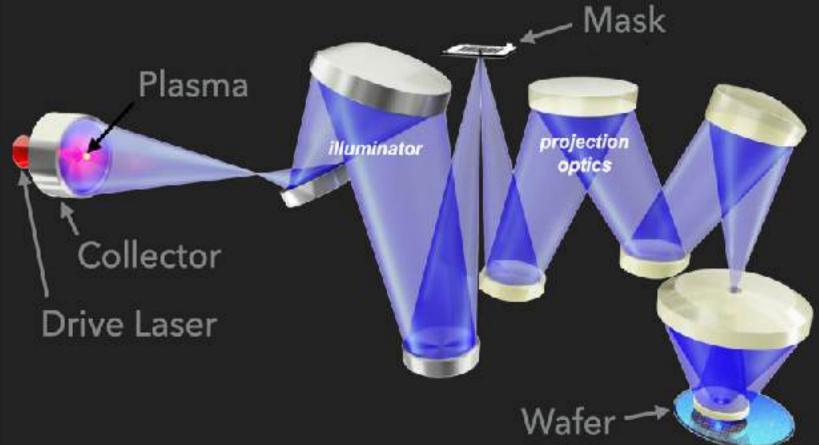
- EUV gets absorbed by matter
- Lenses => Bragg Mirrors
- Single atom layer deposition







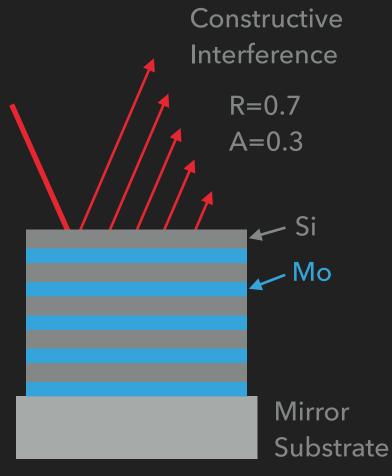


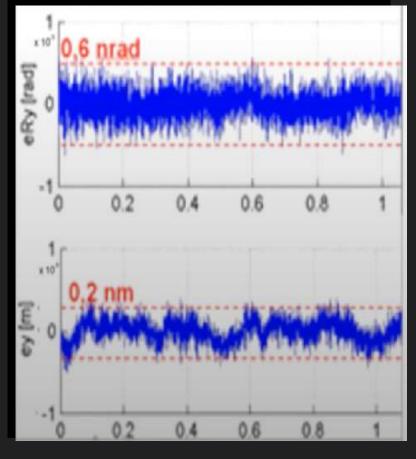


EUV MIRRORS BY ZEISS

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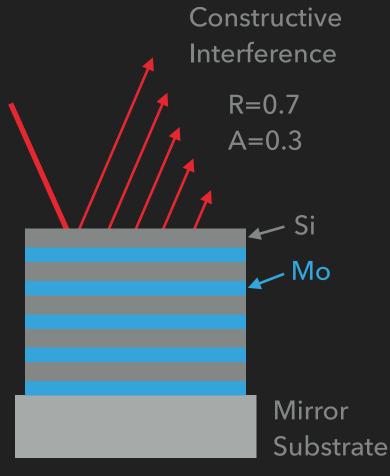


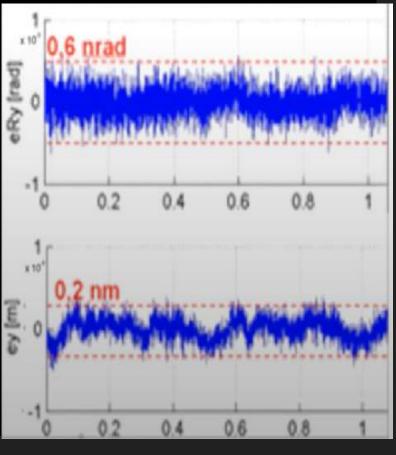


EUV MIRRORS BY ZEISS

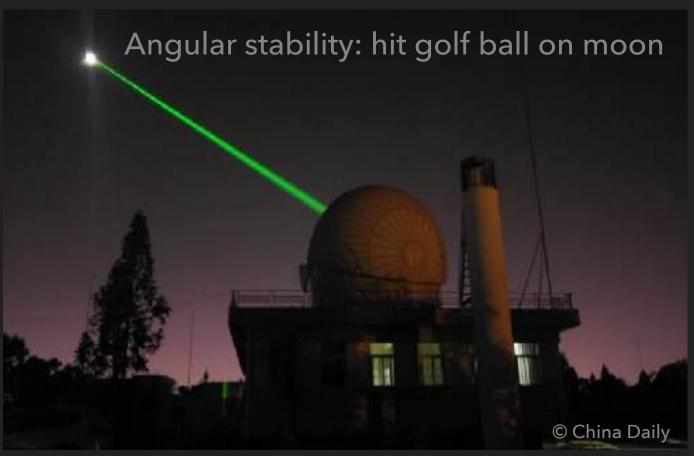
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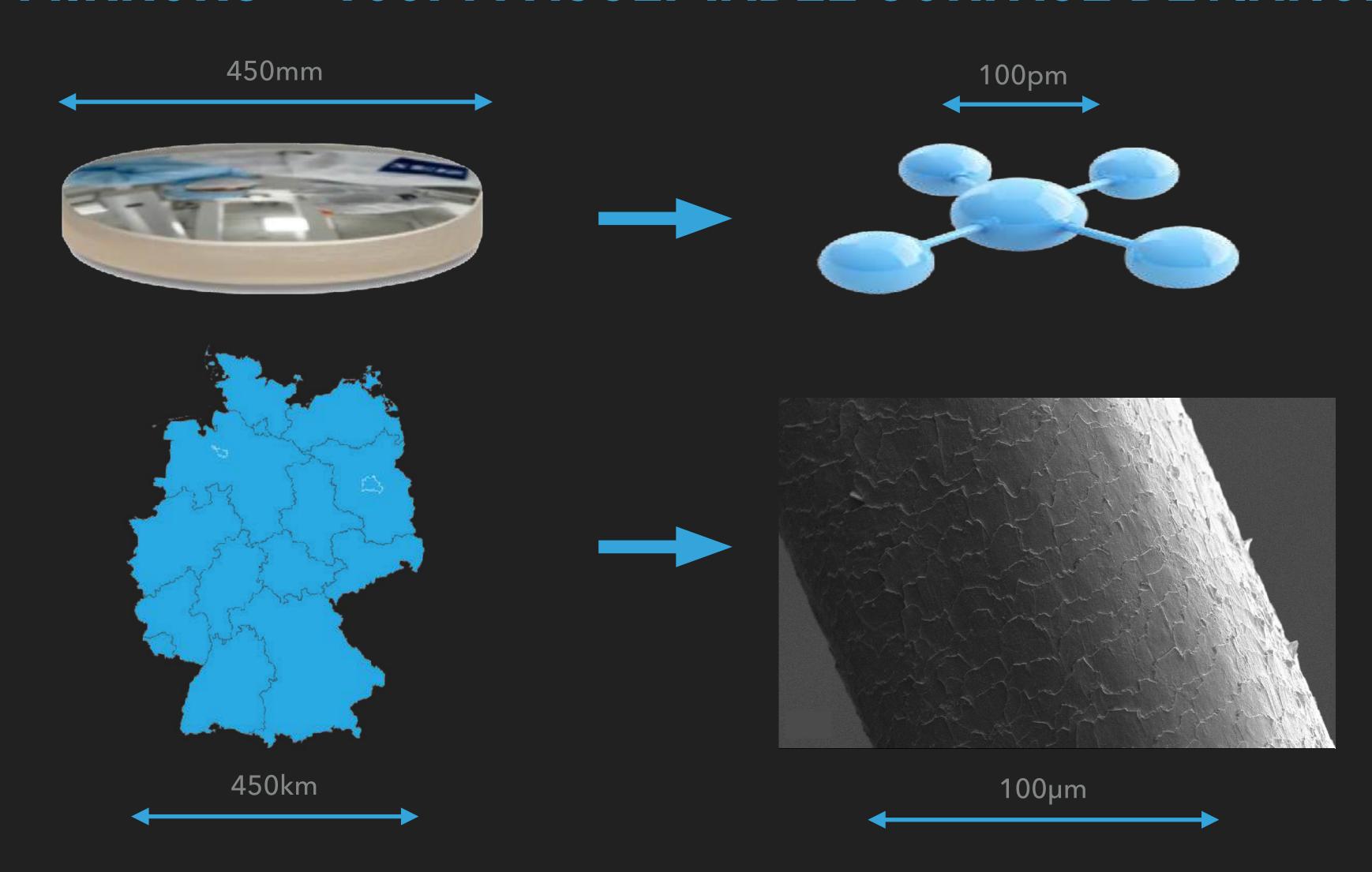




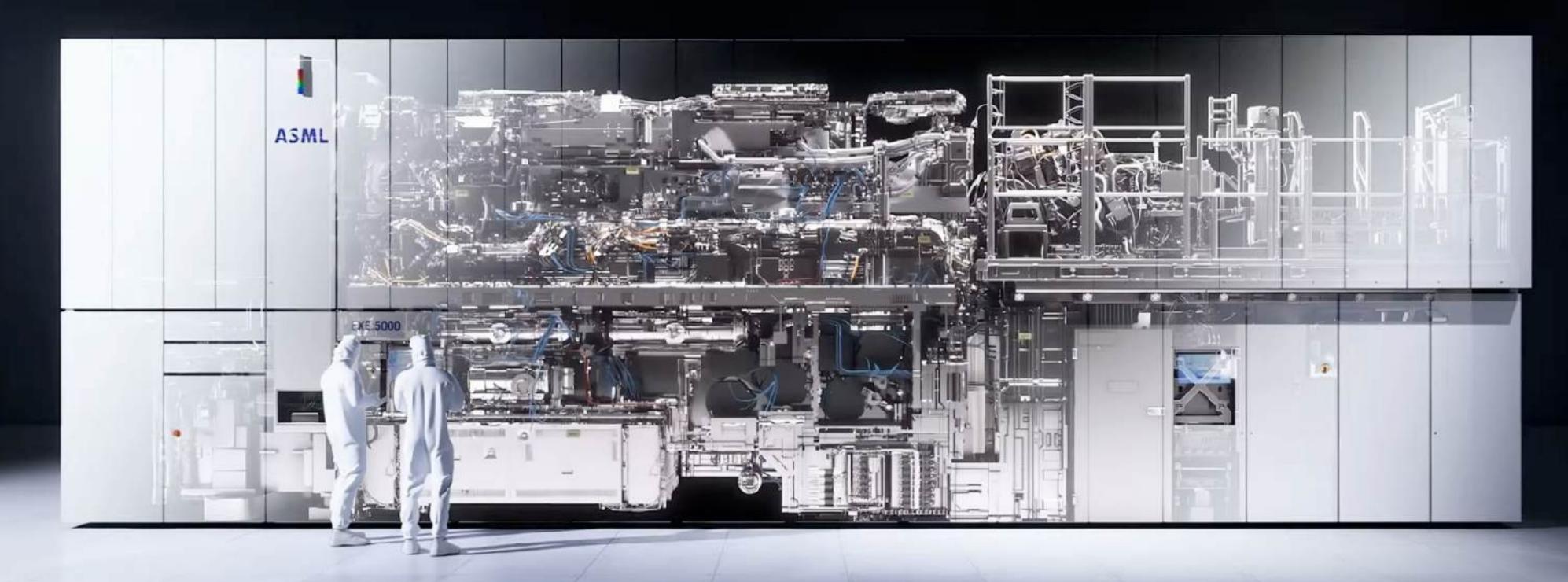




EUV MIRRORS - 100PM ACCEPTABLE SURFACE DEVIATION



PRICE: \$350M



ASML

- Founded by Philipps in 1984
- ► Today worth \$400B





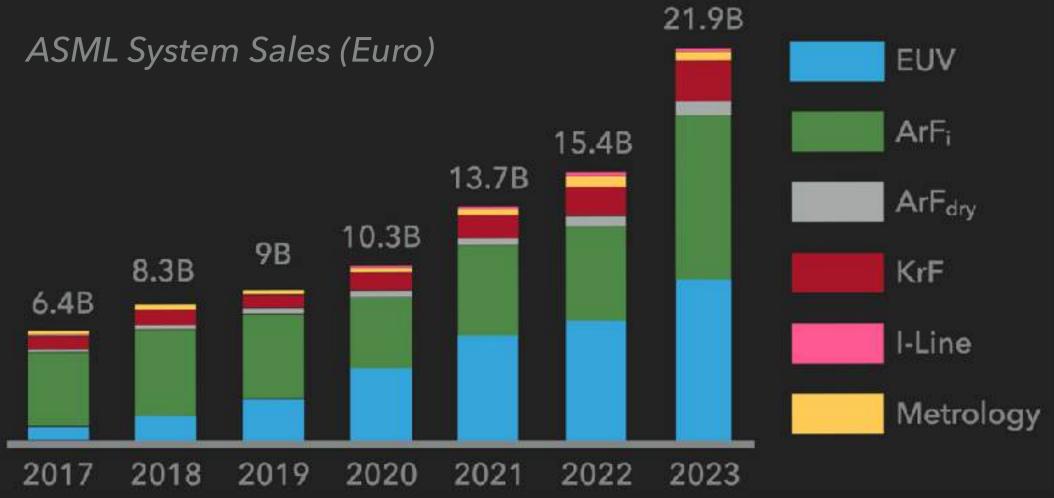
ECONOMICS OF SEMICONDUCTOR FABRICATION

ASML

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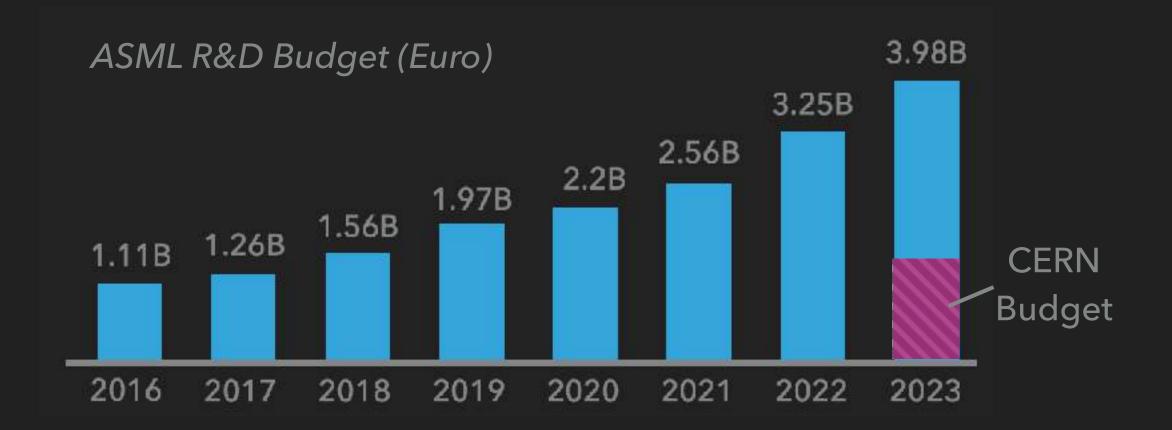


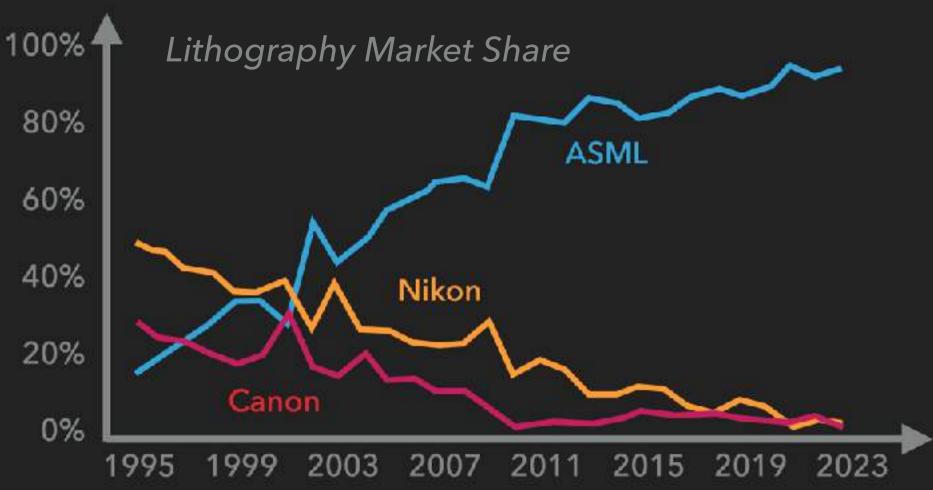


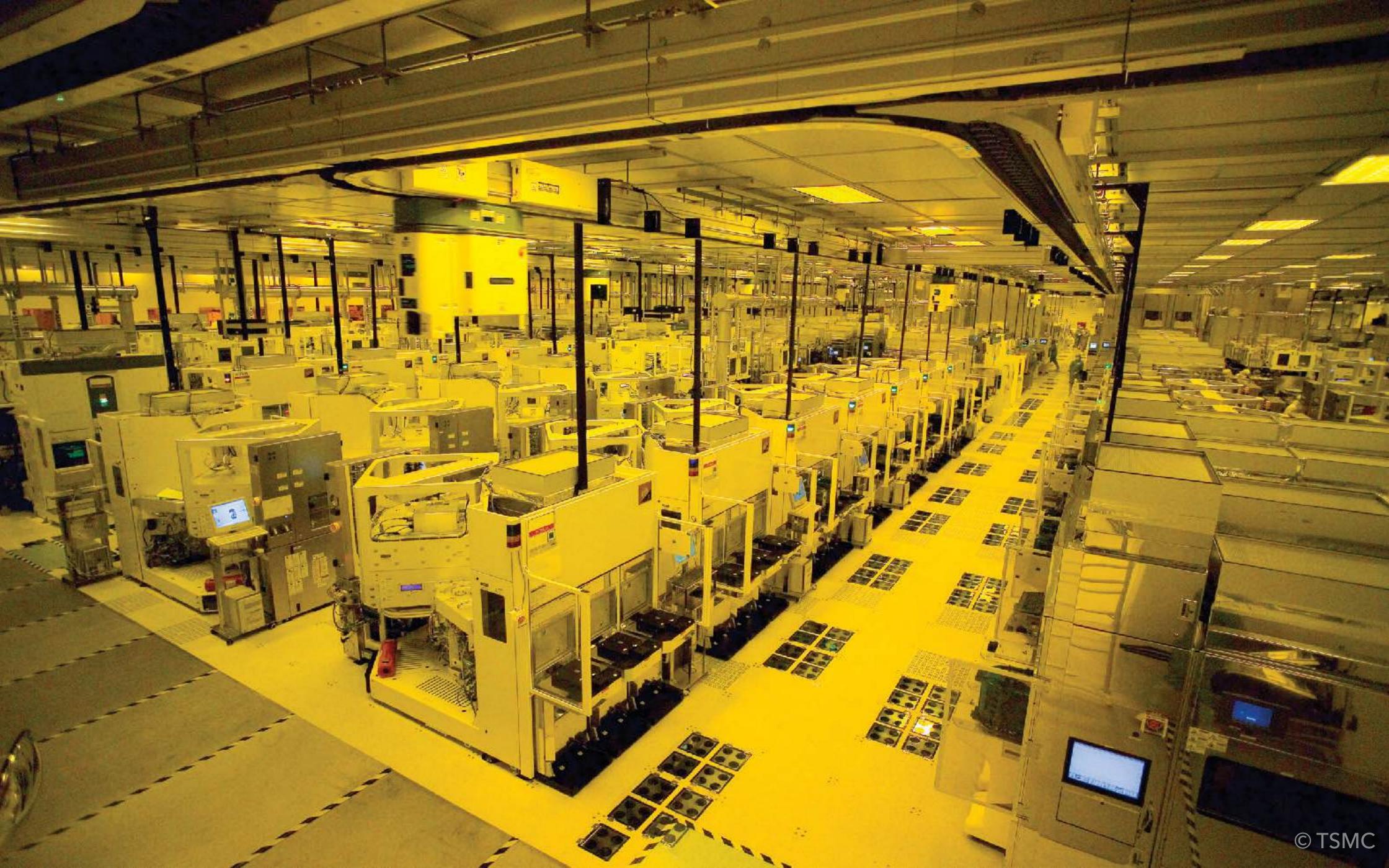
ASML

- Founded by Philipps in 1984
- ▶ Today worth \$400B
- Lithography market share ≈ 90%
- Single source for EUV technology









TSMC

FAB 21, Arizona, USA



TSMC - GIGAFABSTM

FAB Cost: \$20B

▶ FAB Power Consumption: 1GW

► FAB Water Consumption: 8M I/day

▶ FAB Output: 120k Wafer per month



FAB 18, Tainan, Taiwan

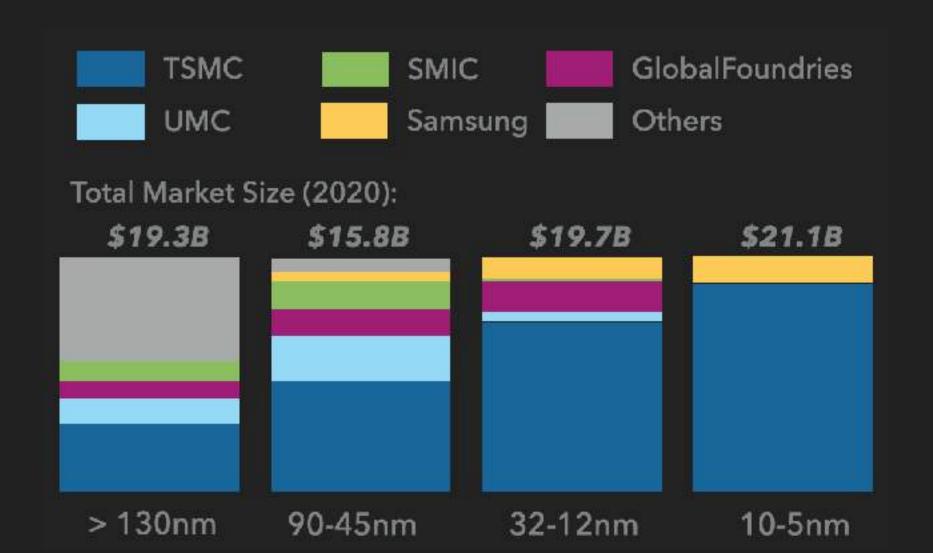
FAB 20, Hsinchu, Taiwan

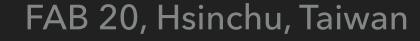




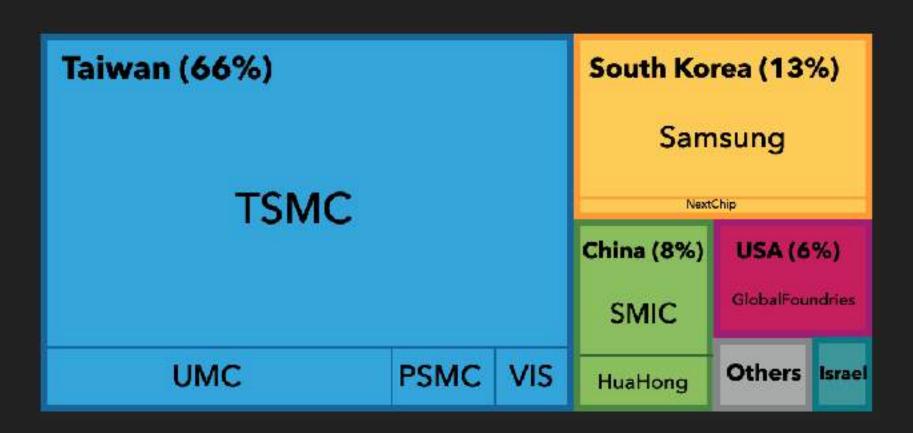
FAB 14, Tainan, Taiwan

- ▶ 60% market share of all chips
- ▶ 92% market share of advanced chips
- Capital Expenditure ≈ \$30B / year
- R&D budget ≈ \$6B / year

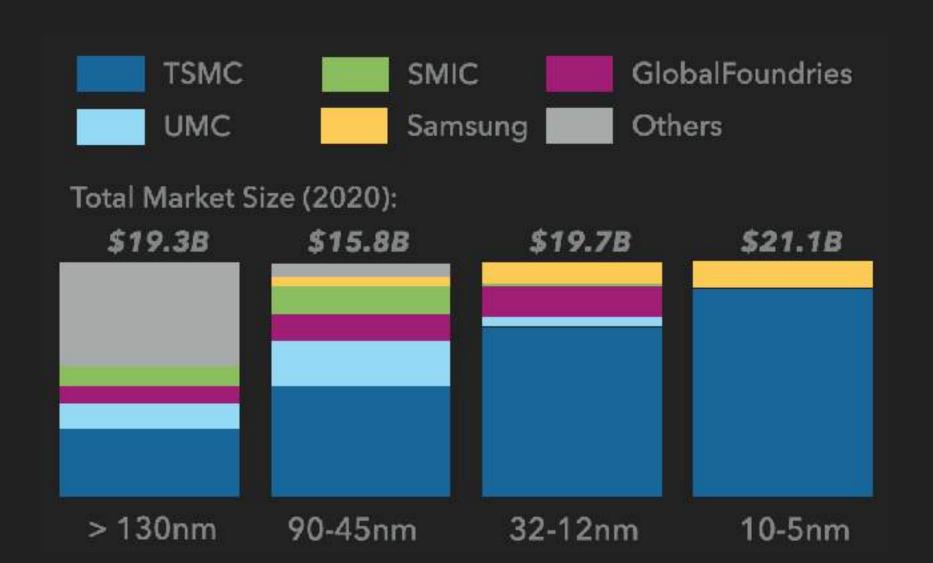


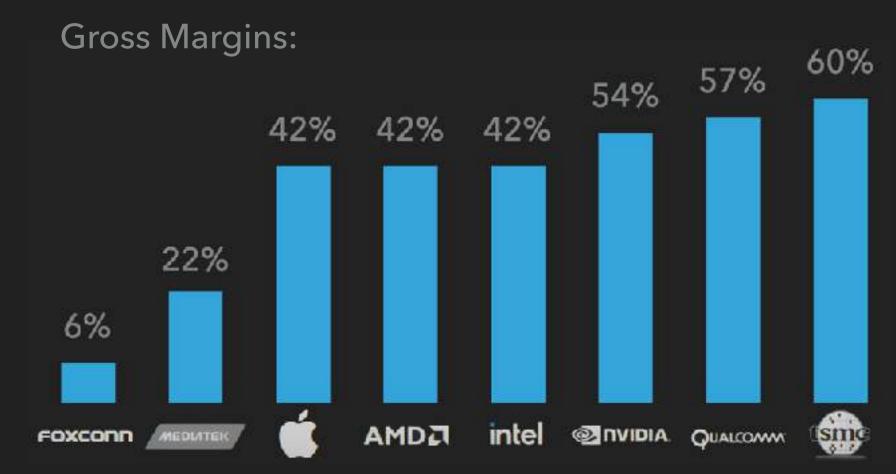


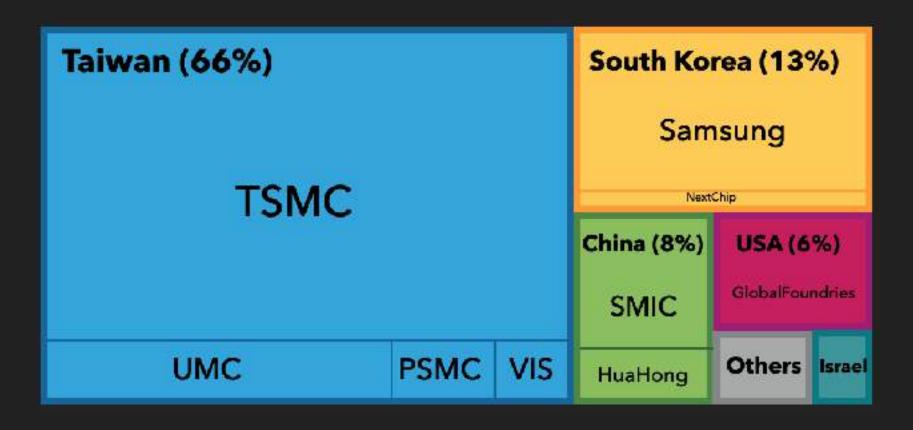




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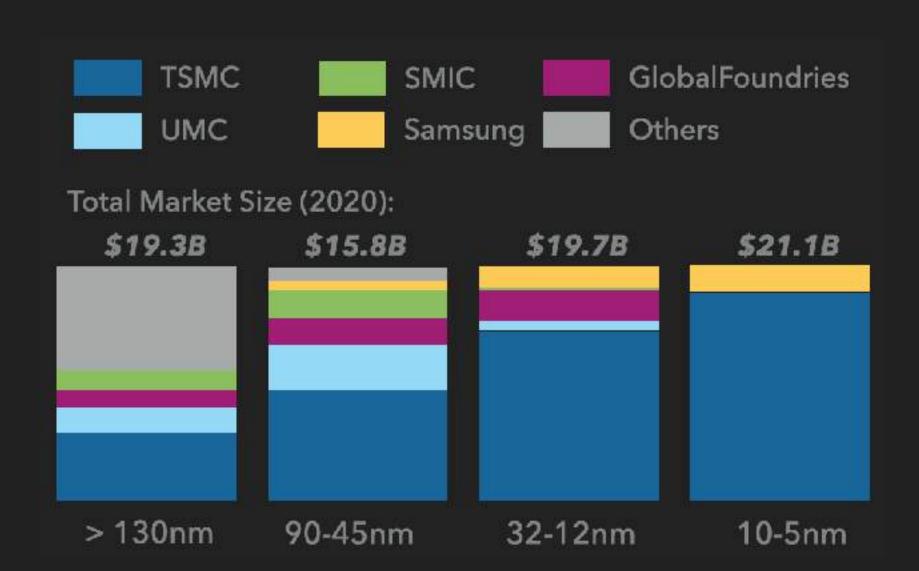


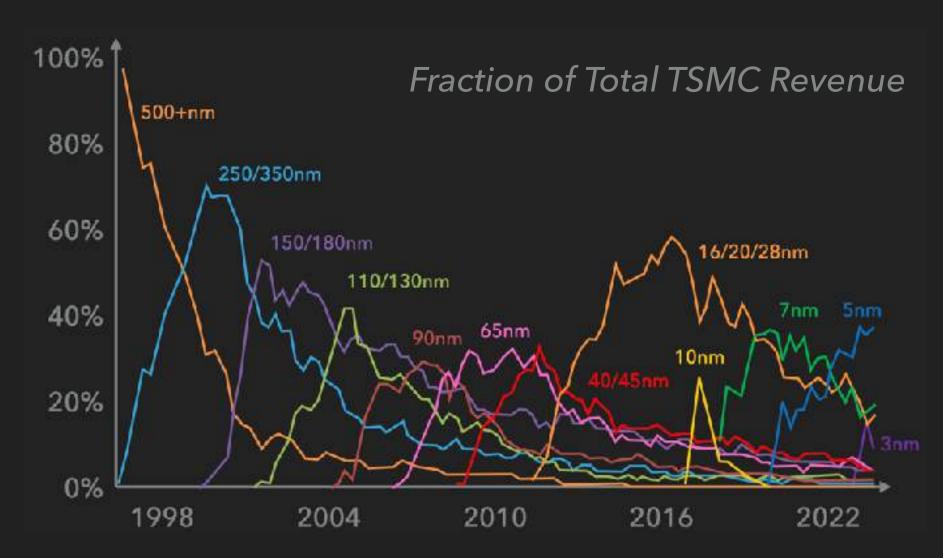


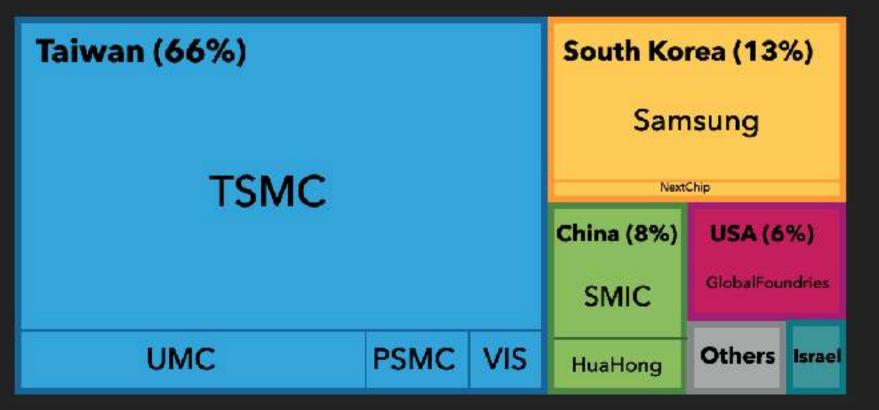


@38C3

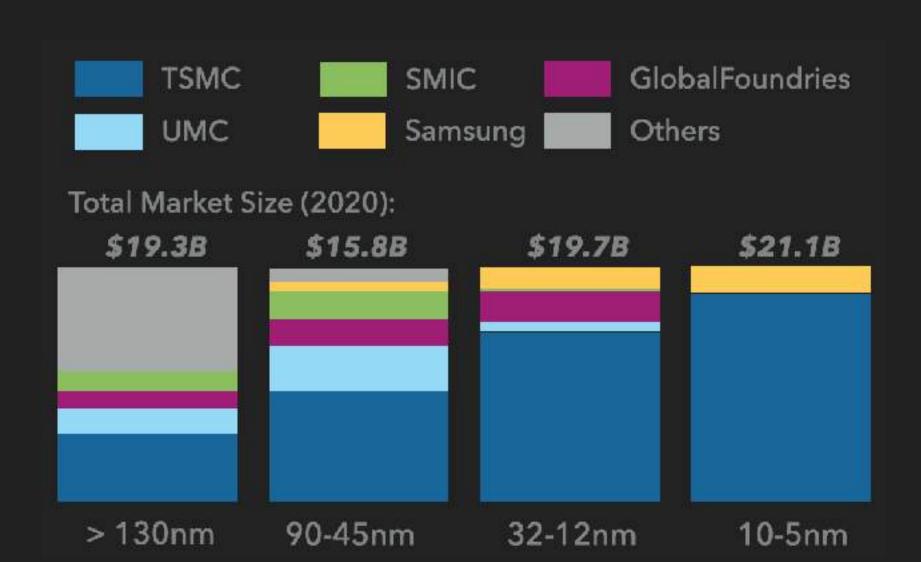
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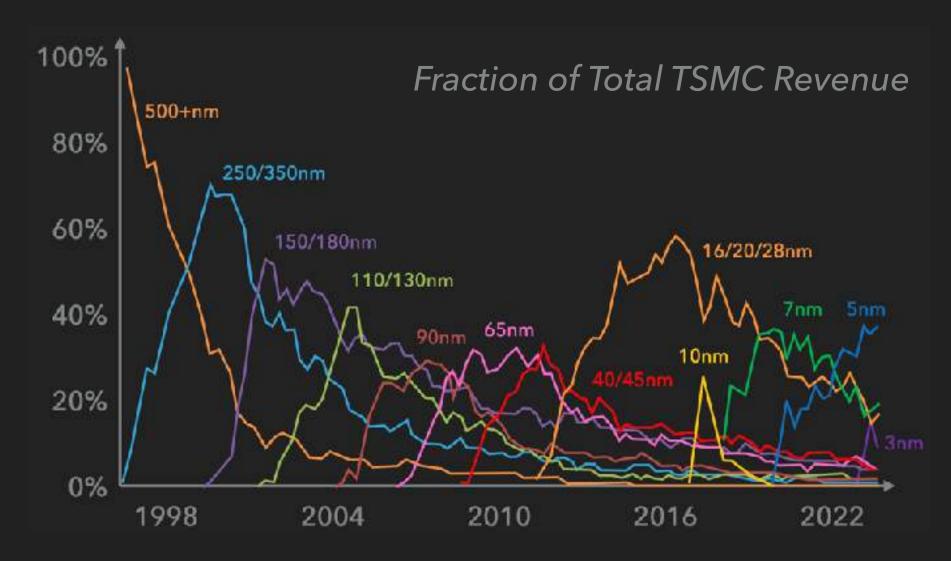


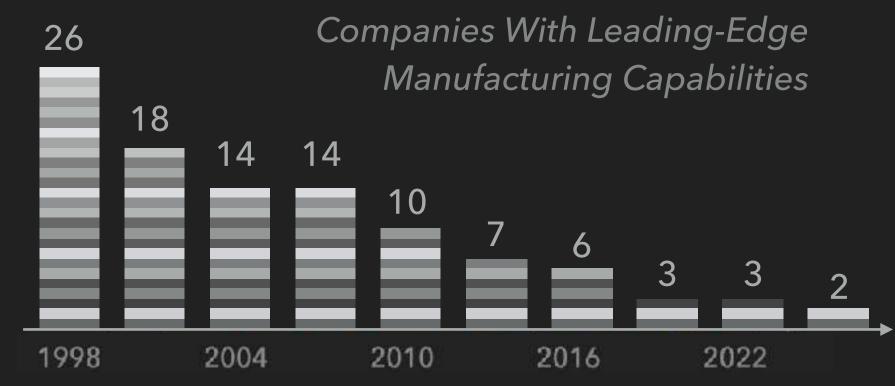




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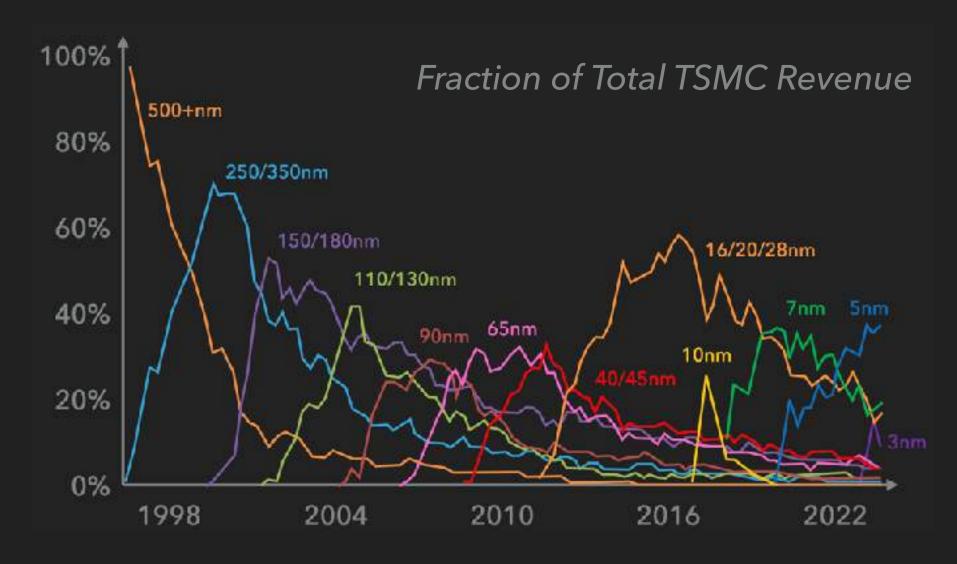


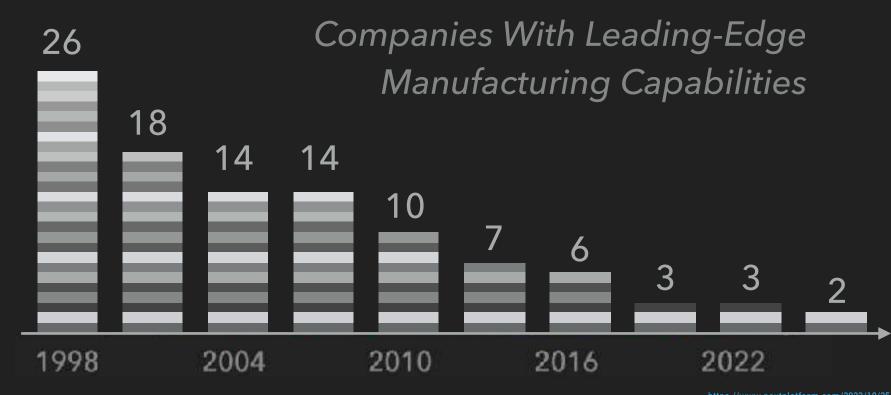




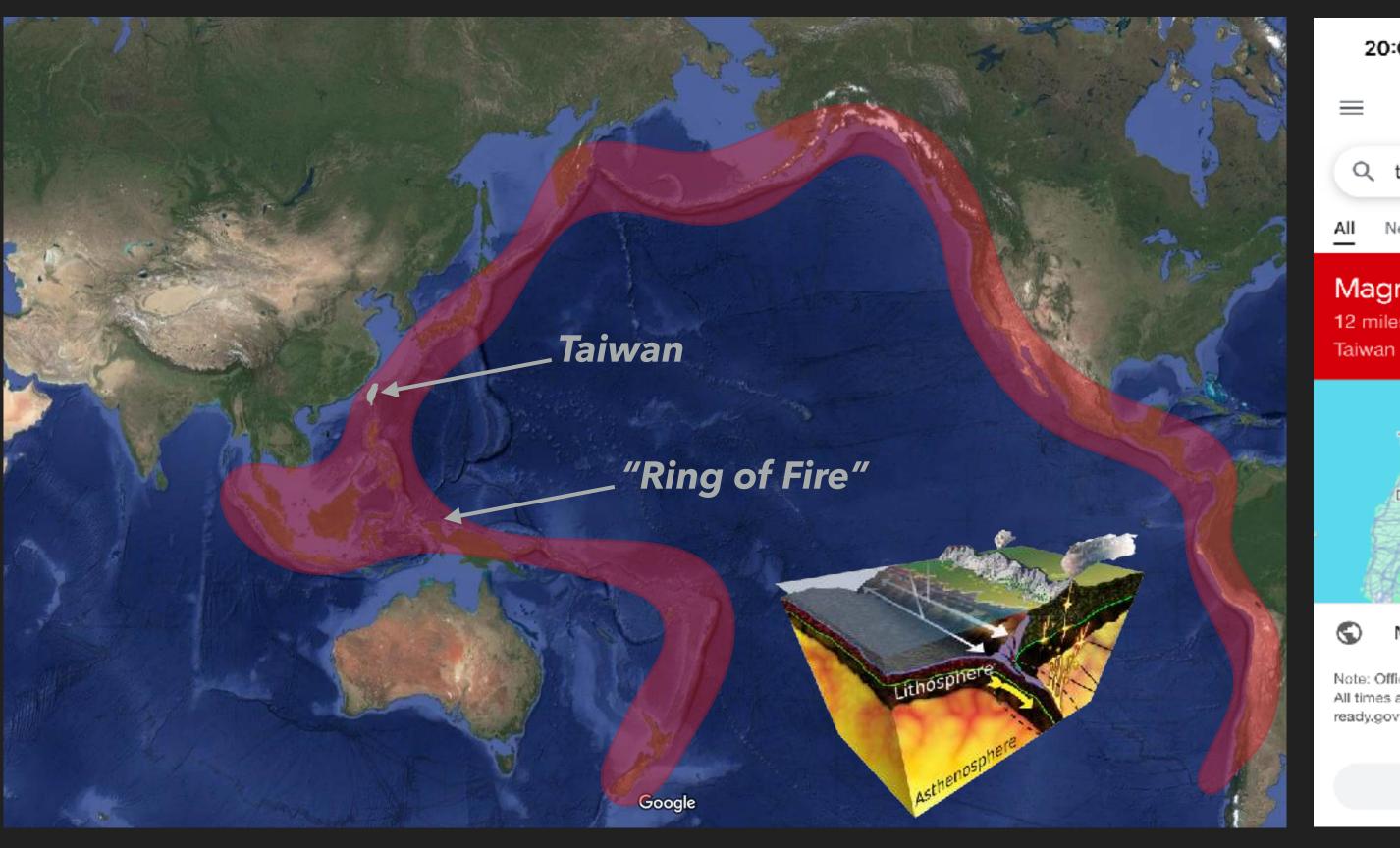
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THE CHIHSHANG FAULT





THE CHIHSHANG FAULT







3. April 2024 - 7.2 earthquake



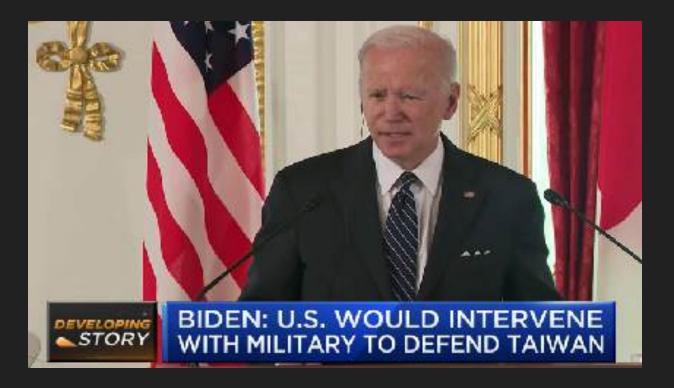


PIECE IN THE TAIWAN STRAIGHT



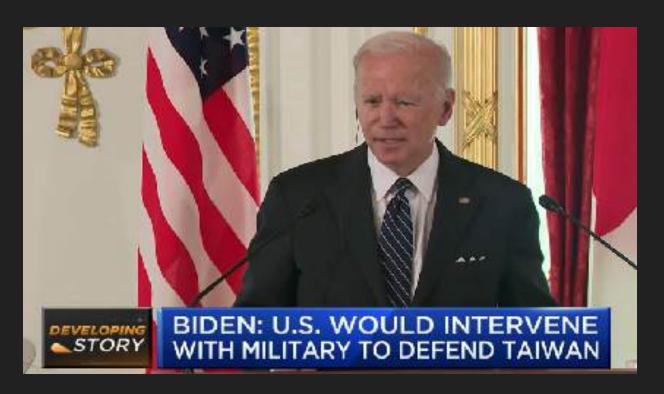


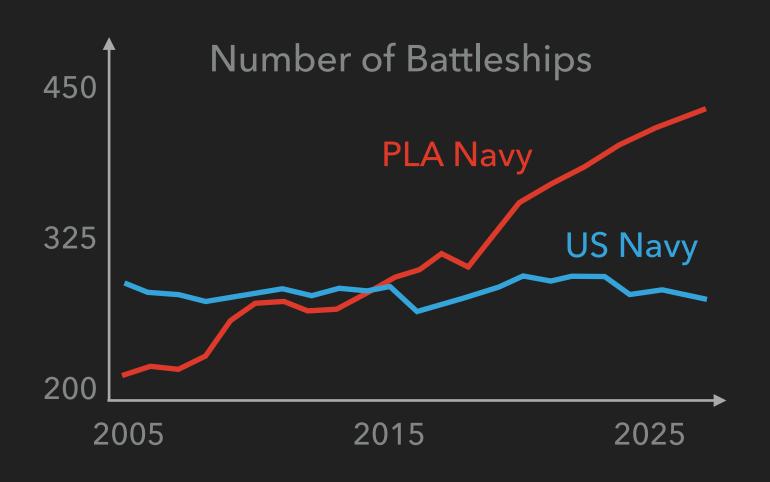


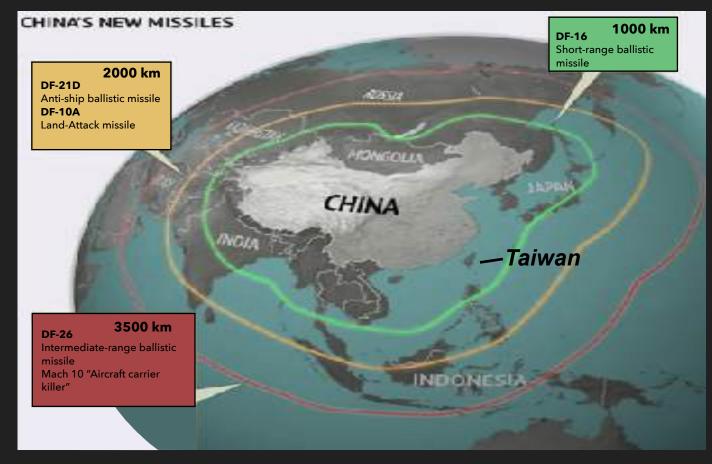






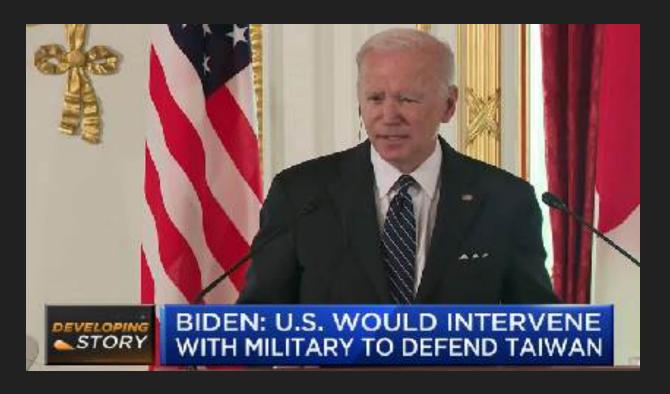




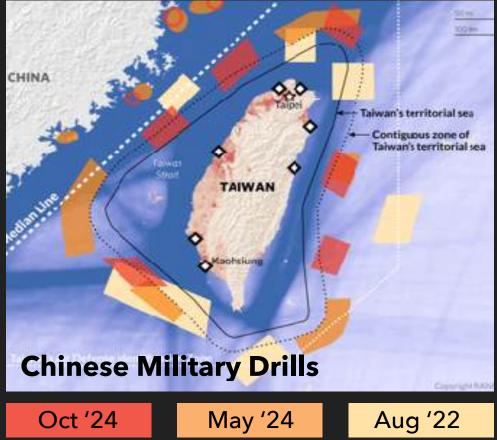








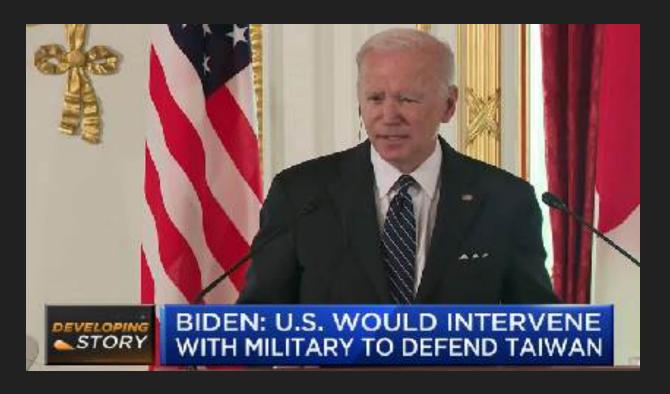




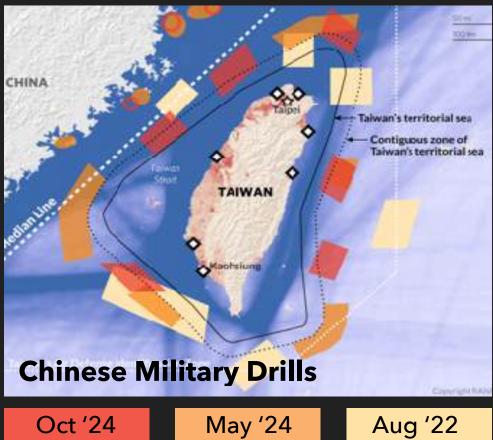








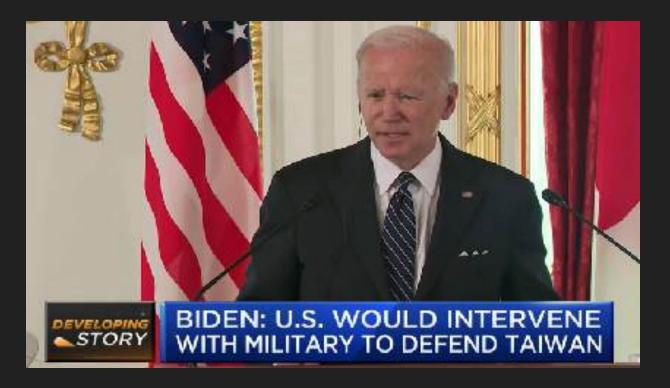










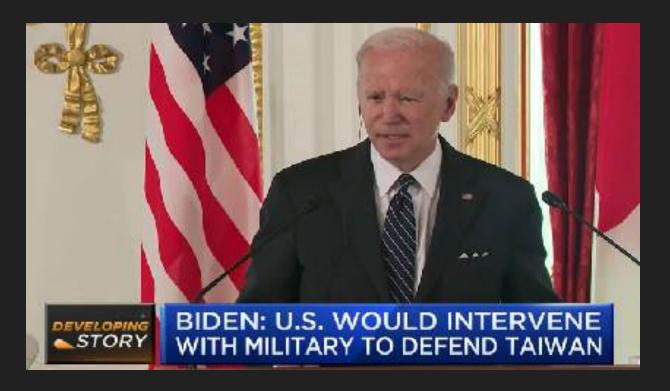




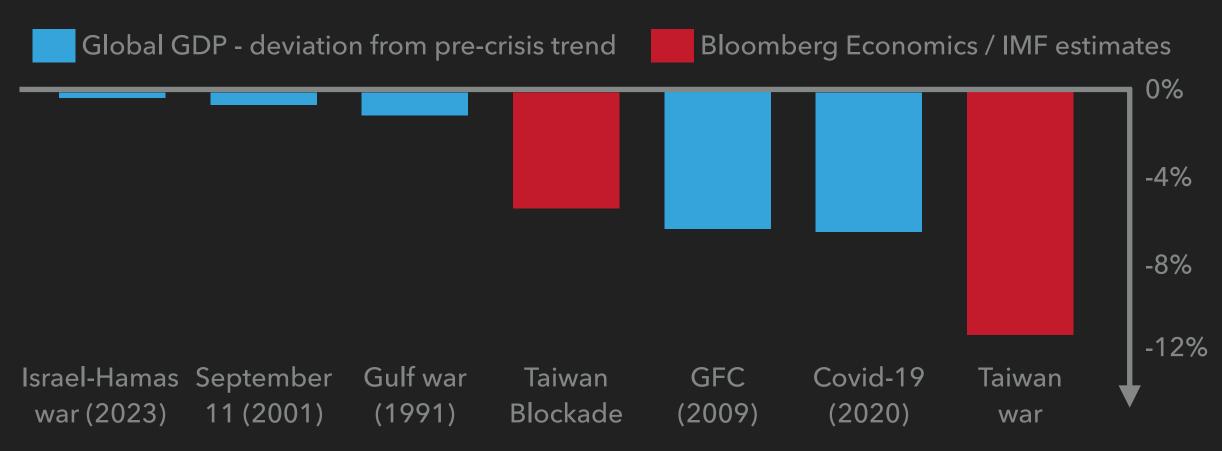










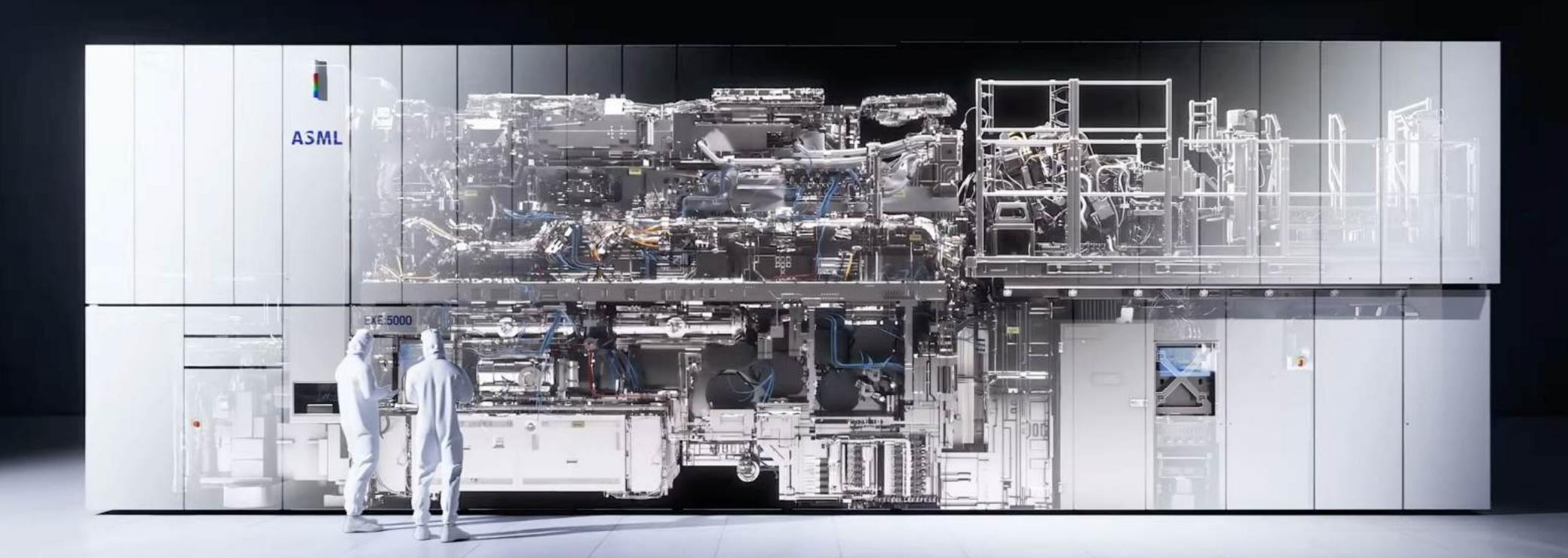


"ANY SUFFICIENTLY ADVANCED TECHNOLOGY IS INDISTINGUISHABLE FROM MAGIC" ARTHUR C. CLARKE





THANKS FOR YOUR ATTENTION



SPECIAL THANKS TO:

Asianometry: https://www.youtube.com/asianometry

Semislides: https://www.youtube.com/@SemiSlides

Chris Miller: "Chip War: The Fight for the World's Most Critical Technology"

Contact: thellert@lbl.gov